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(54) **TRANSMITTER-RECEIVER CIRCUIT FOR RADIO COMMUNICATION AND SEMICONDUCTOR INTEGRATED CIRCUIT DEVICE**

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This patent is subject to a terminal disclaimer.

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(51) **Int. Cl.**<sup>7</sup> ..... **H04B 1/48**

(52) **U.S. Cl.** ..... **455/83; 455/78; 455/129**

(58) **Field of Search** ..... 455/78, 80, 82, 455/83, 84, 89, 90, 129; 333/101, 103, 104

(56) **References Cited**

**U.S. PATENT DOCUMENTS**

4,637,073	A	*	1/1987	Selin et al.	.....	455/78
5,442,812	A	*	8/1995	Ishizaki et al.	.....	455/82
5,444,740	A	*	8/1995	Mizukami et al.	.....	375/286
5,594,394	A	*	1/1997	Sasaki et al.	.....	333/103
5,784,687	A	*	7/1998	Itoh et al.	.....	455/78

**FOREIGN PATENT DOCUMENTS**

JP	04373317	12/1992
JP	6-169266	6/1994
JP	06237101	8/1994

**OTHER PUBLICATIONS**

P.S. Bachert, "Wireless Antenna Interface". Applied Microwave & Wireless, pp. 24, 26, 28-30, 32 and 35, Fall 1994.

\* cited by examiner

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(57) **ABSTRACT**

A transmitter-receiver circuit for radio communication, comprising a low-noise receiver amplifier (20); a first matching circuit (40) which converts the input impedance of the amplifier (20); a transmitter amplifier (10) including a second matching circuit (50) and a third matching circuit (60) which convert the impedances to transmitting signals; and a mode switch (30) for changing from transmitting to receiving and vice versa. The transmitter amplifier (10) has a control terminal (14) connected to the gate electrode of a high-power FET (12), and the output terminal (15A) of the terminal (10) is connected to an antenna (80) not through the switch (30).

**4 Claims, 11 Drawing Sheets**

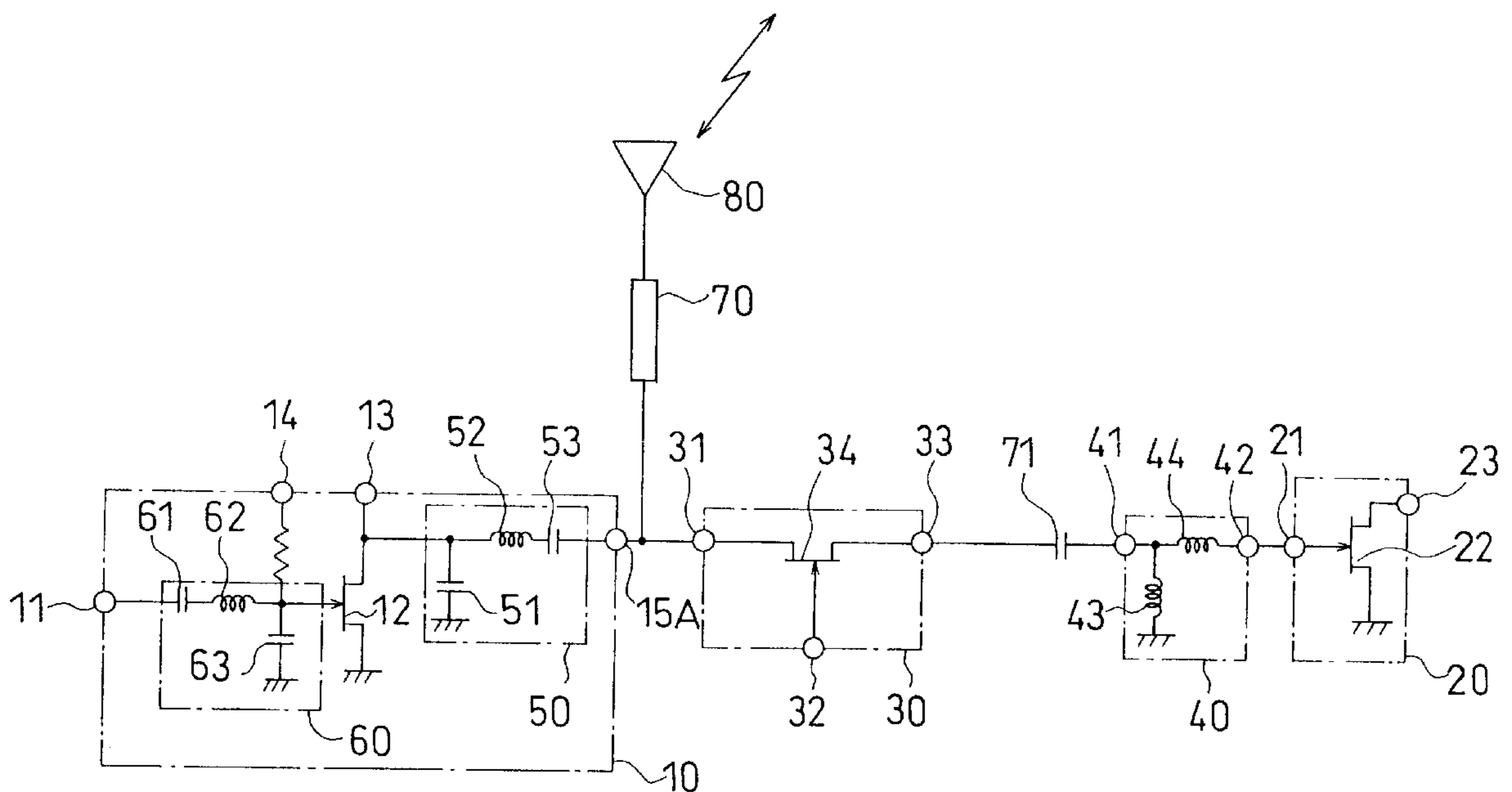


Fig. 1

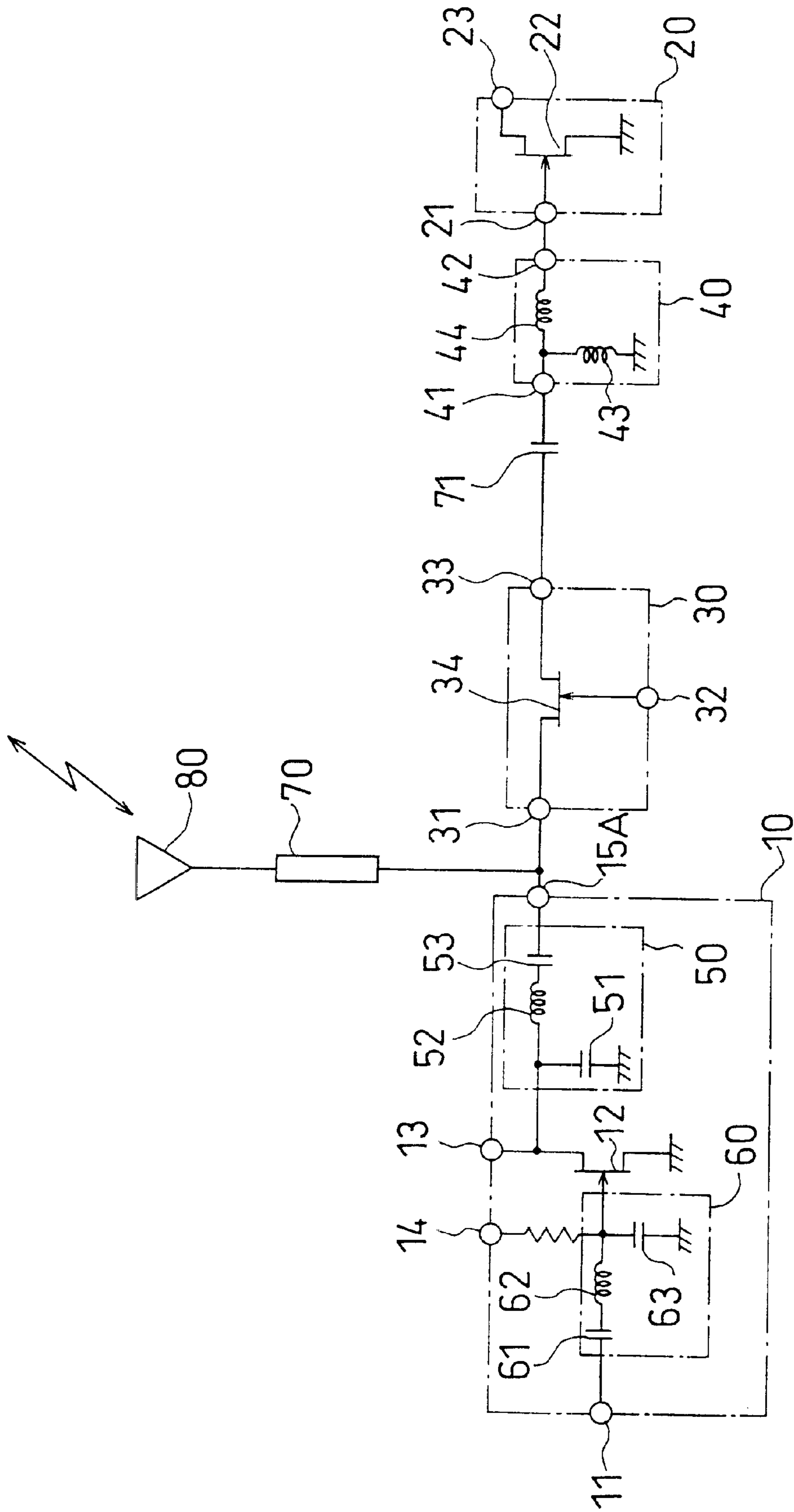


Fig. 2

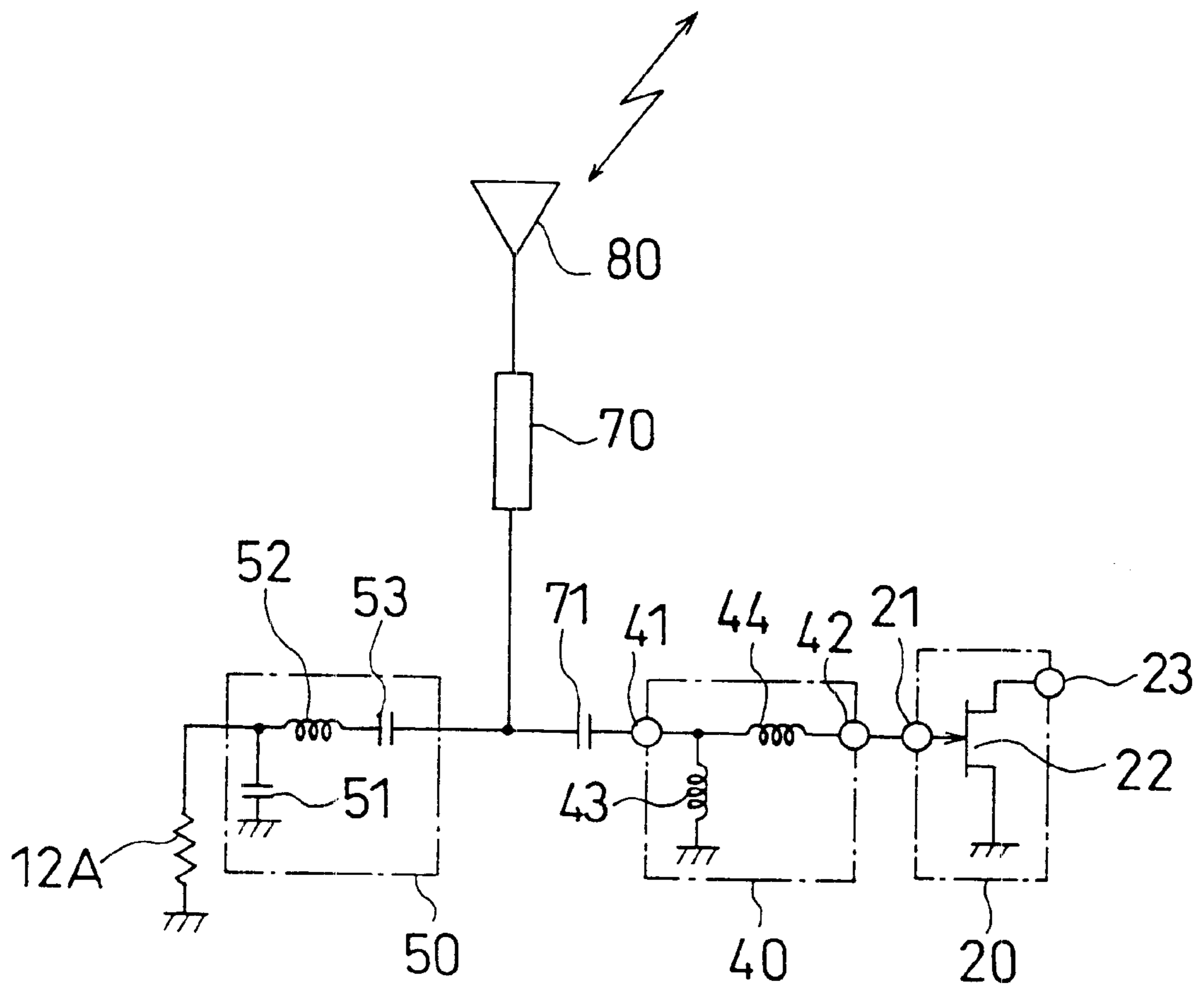


Fig. 3

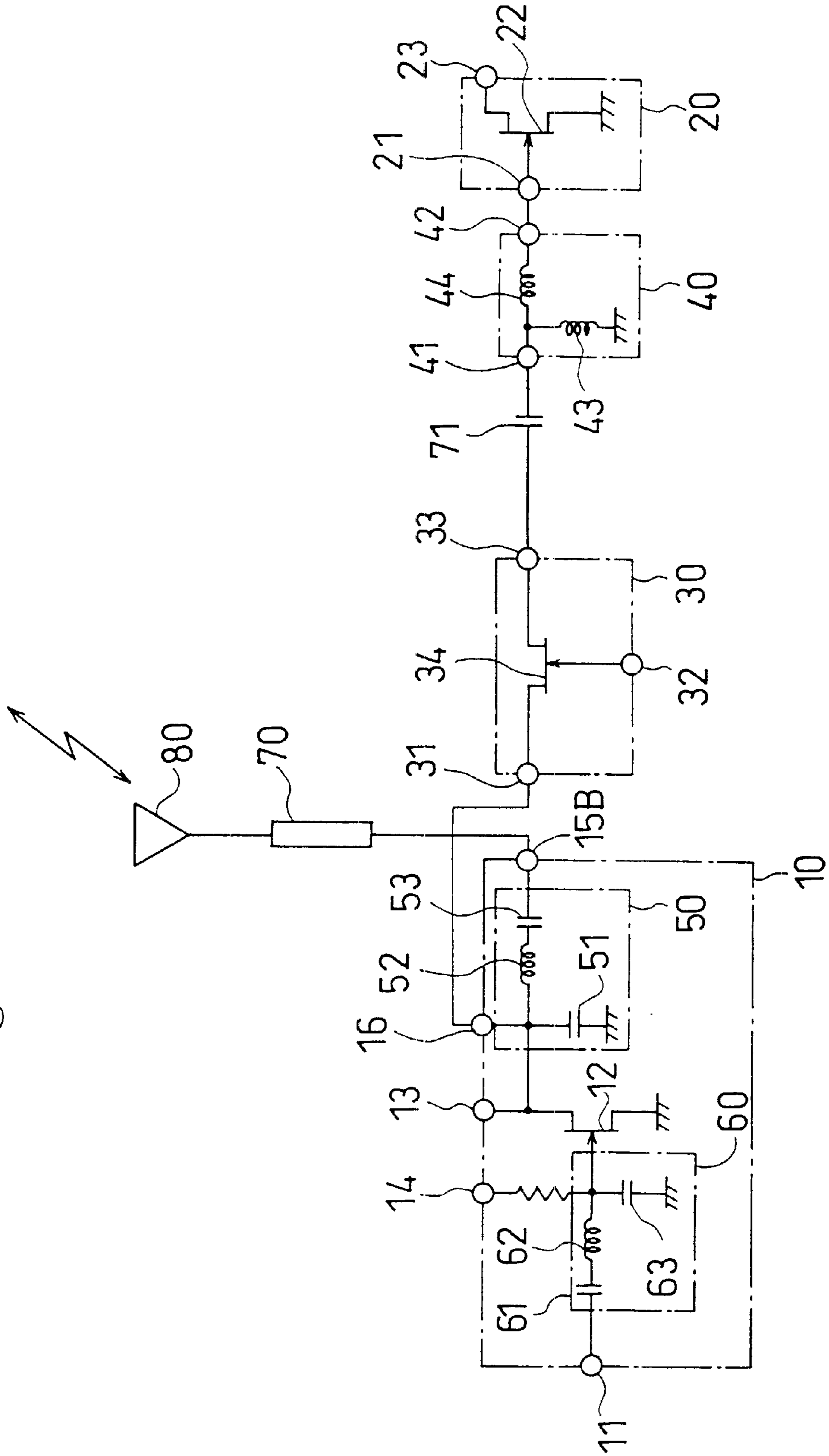


Fig. 4

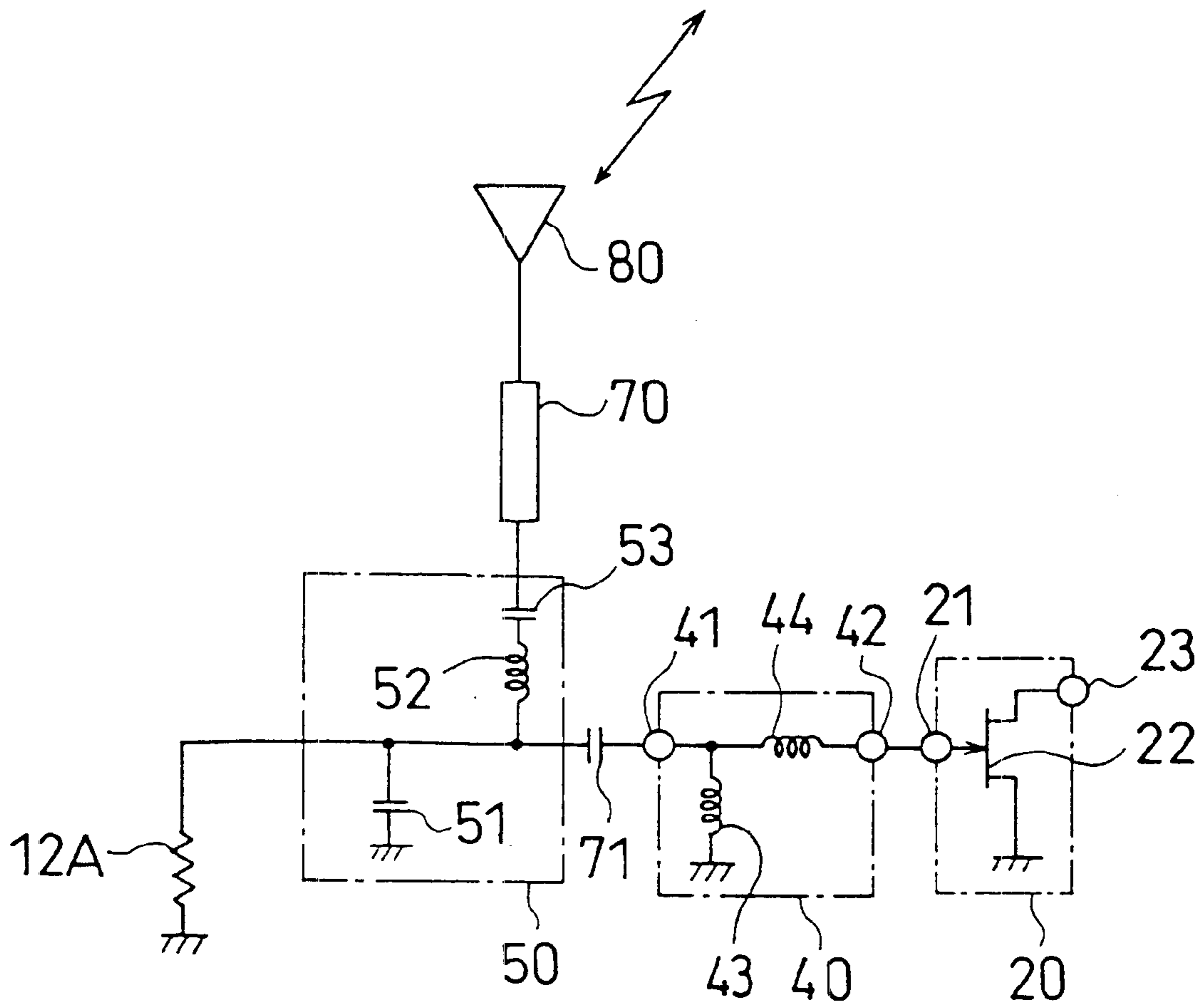


Fig. 5(a)

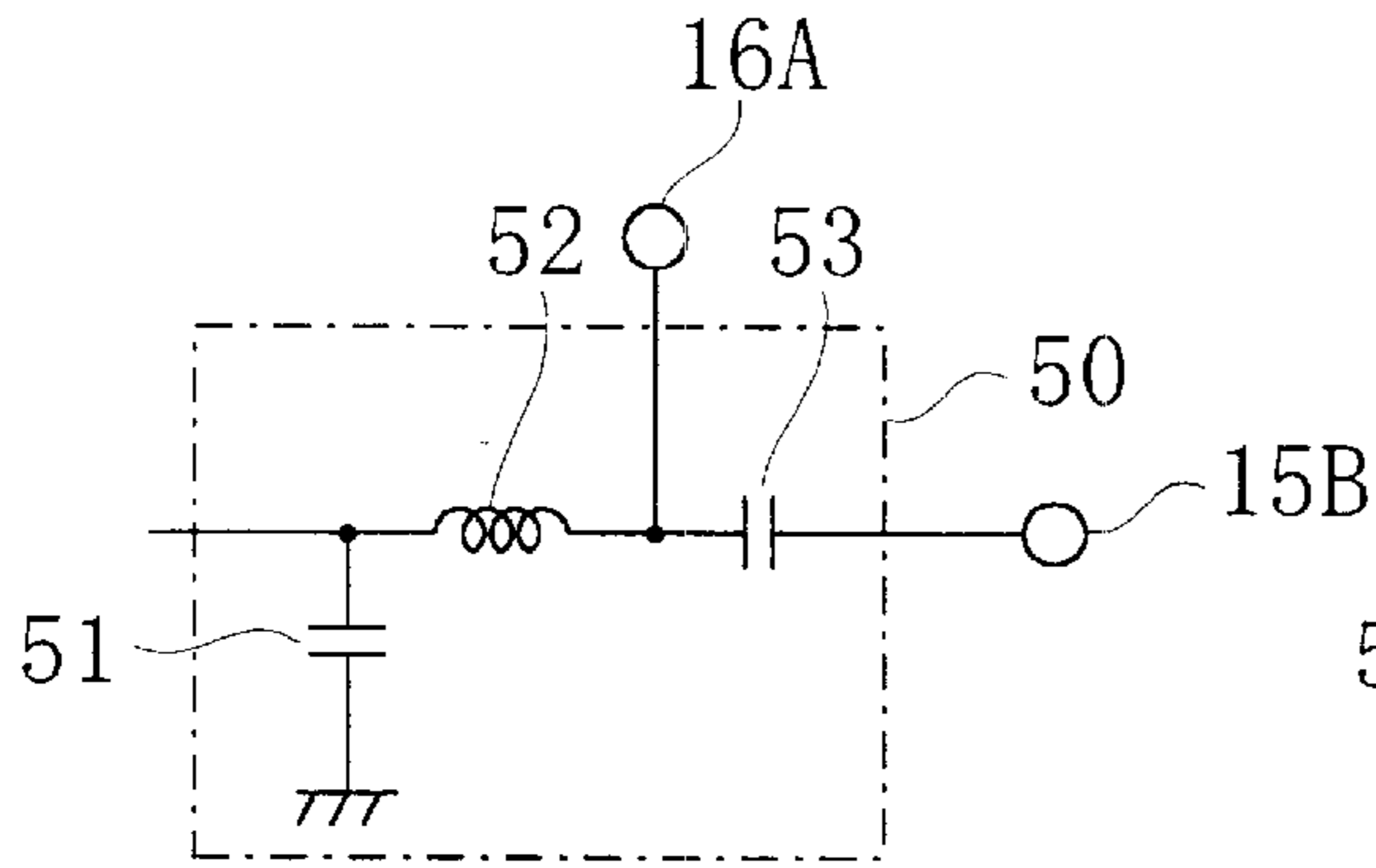


Fig. 5(b)

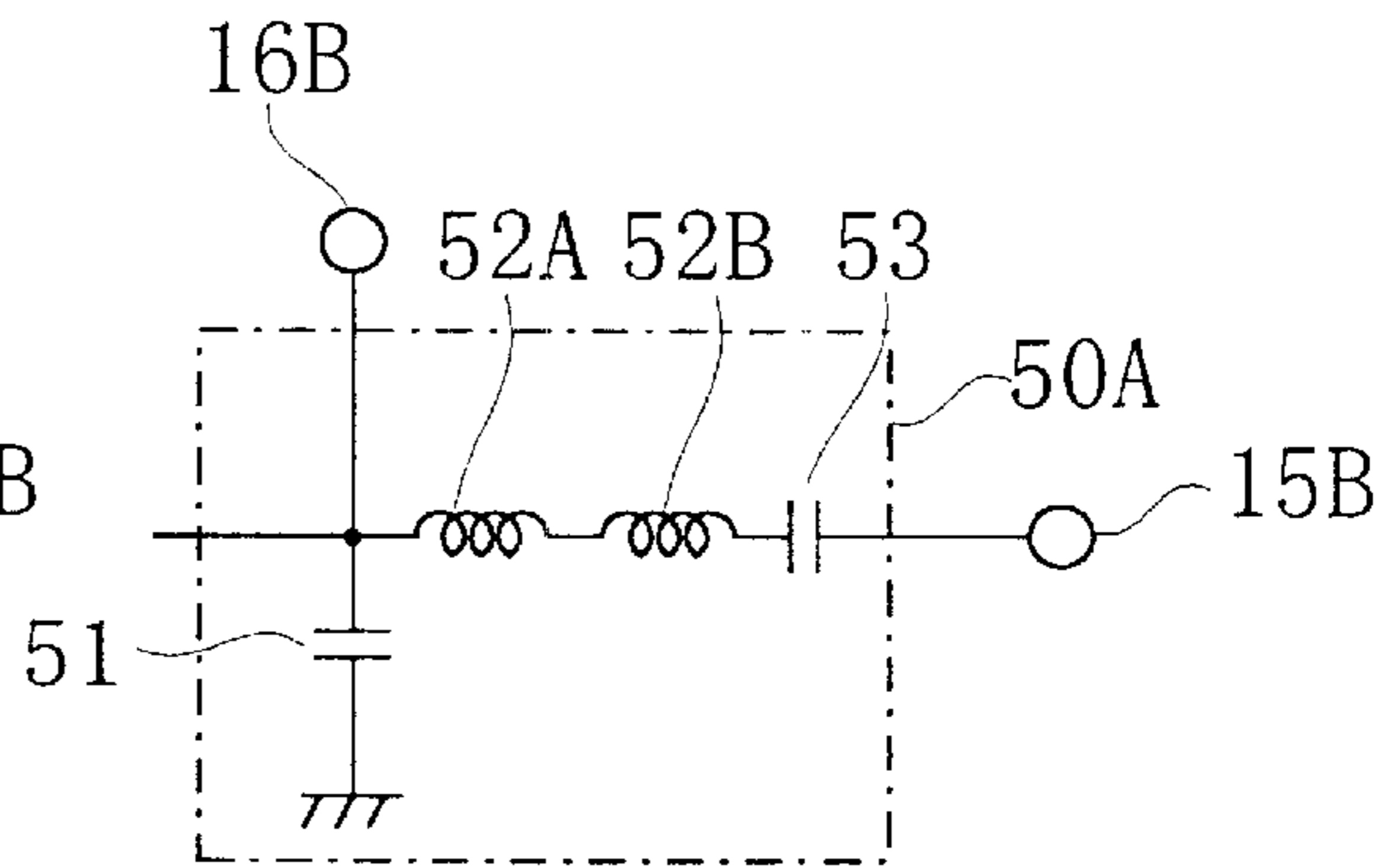


Fig. 5(c)

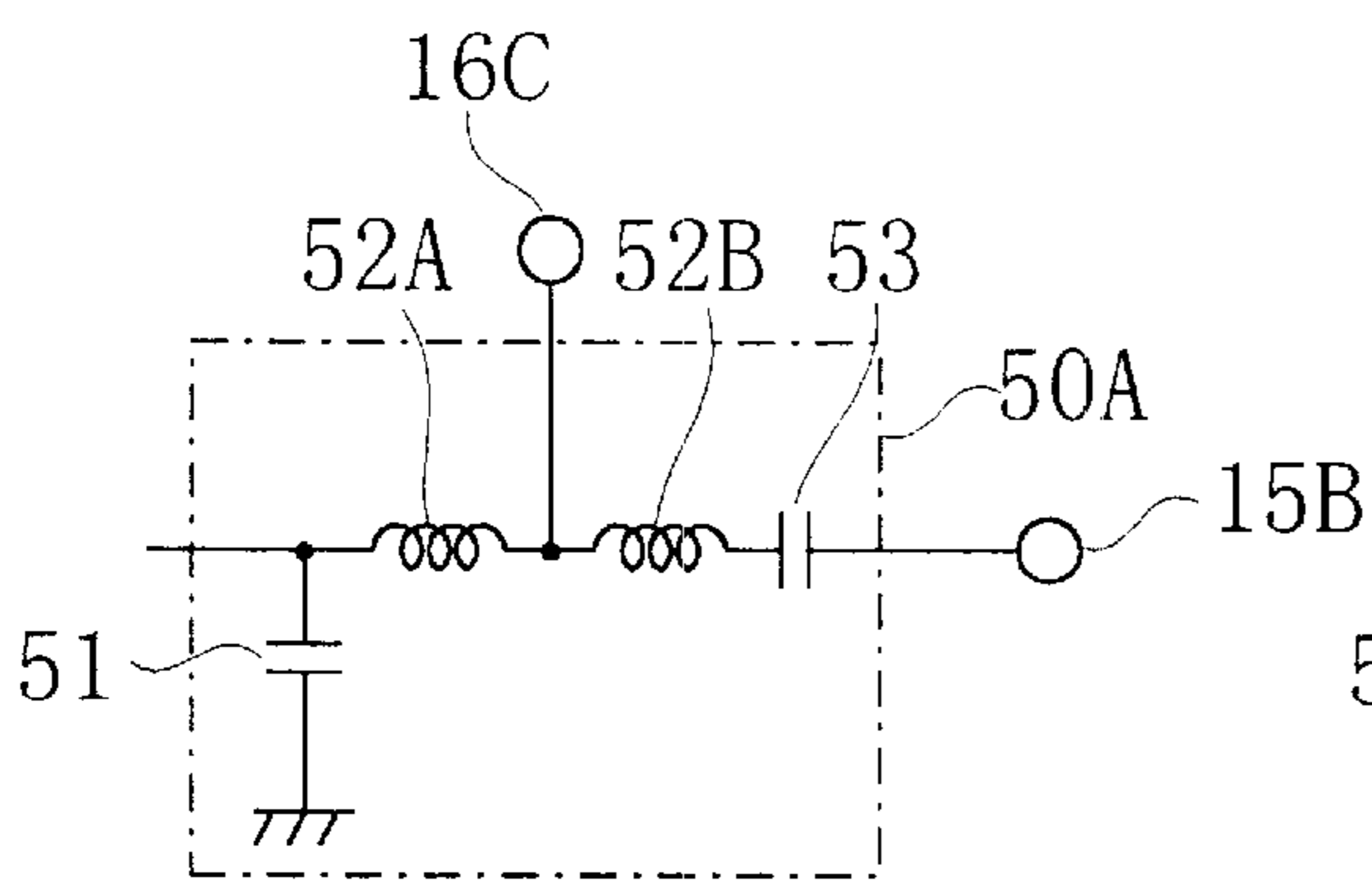


Fig. 5(d)

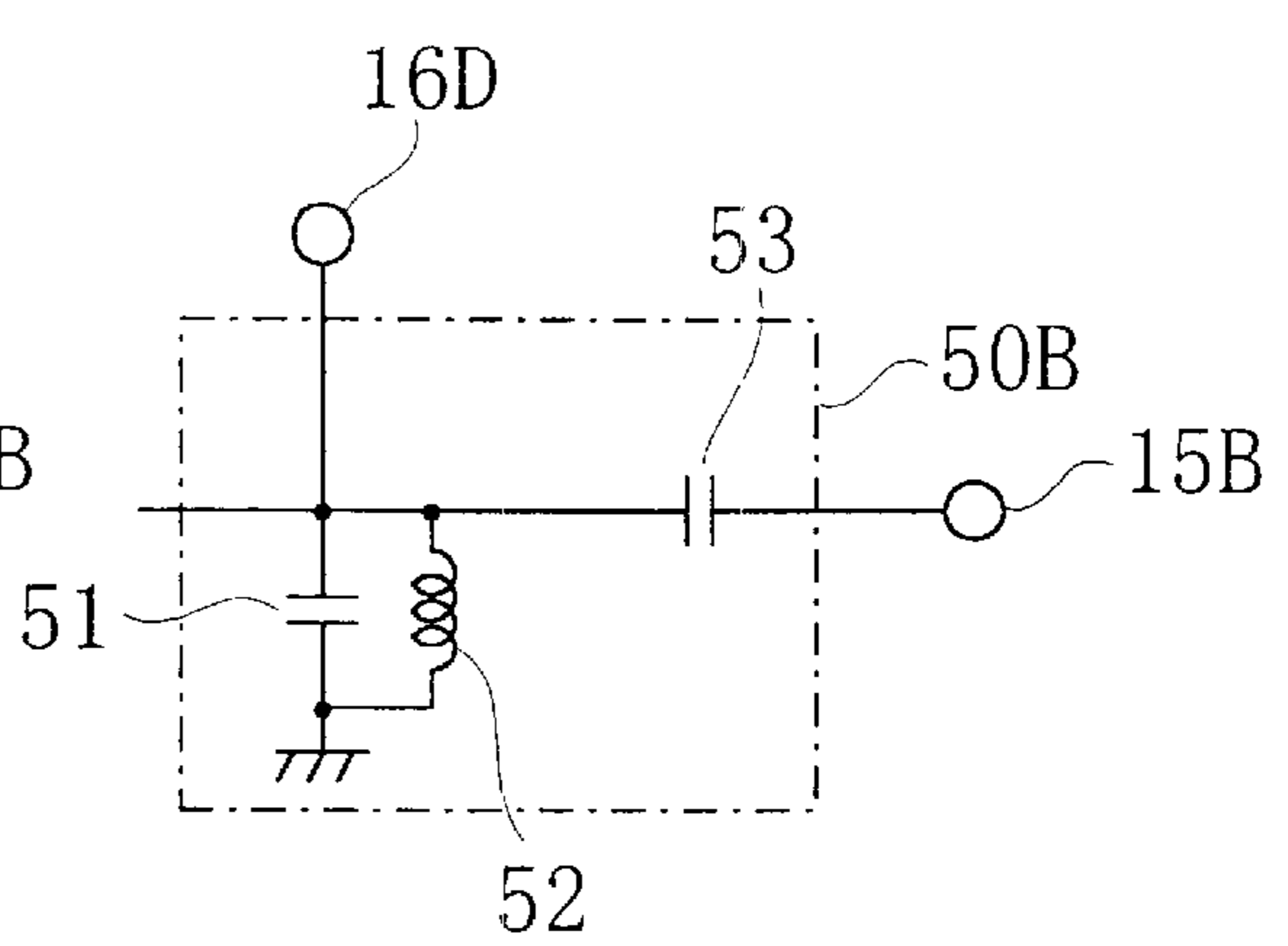


Fig. 6(a)

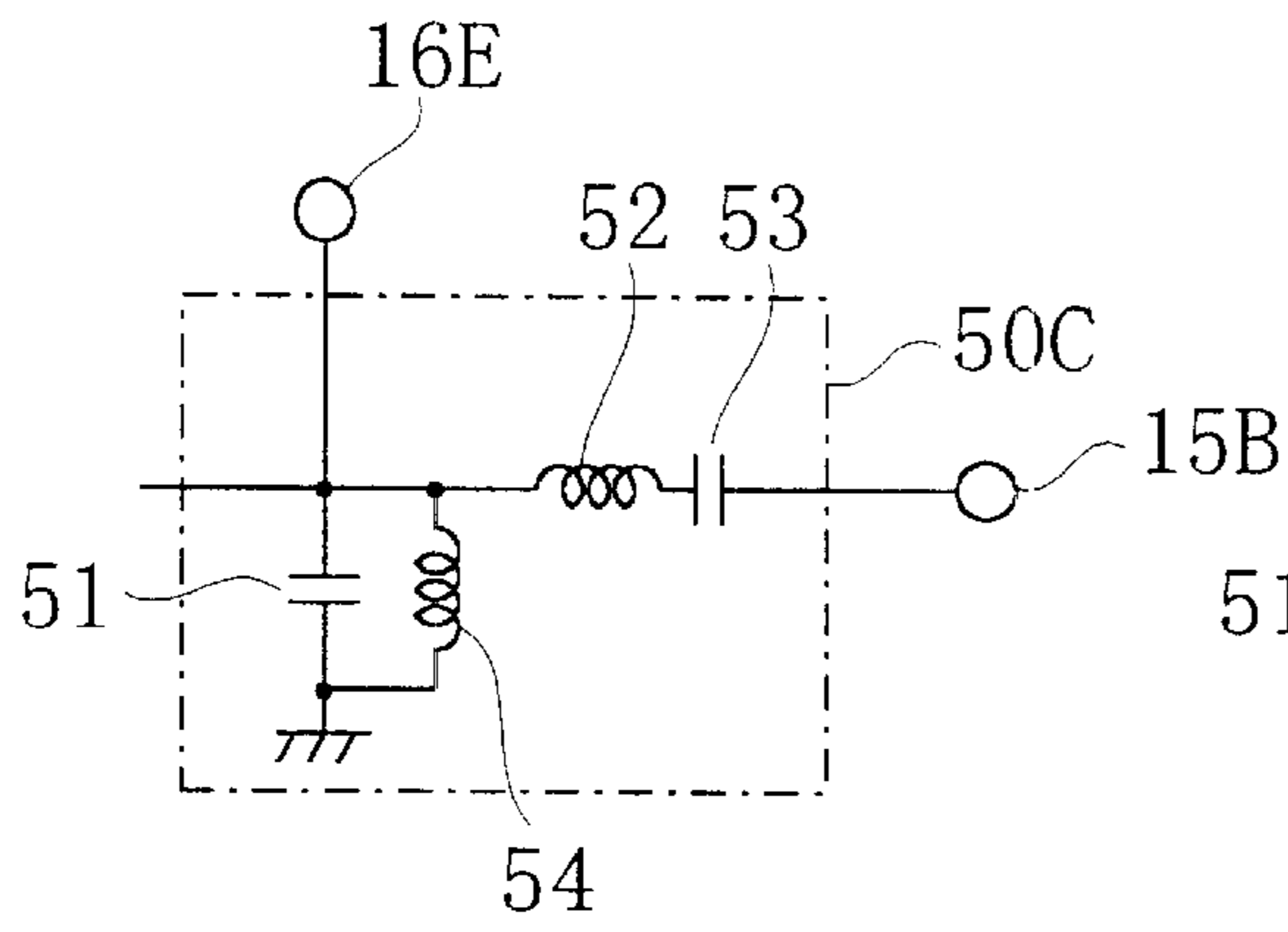


Fig. 6(b)

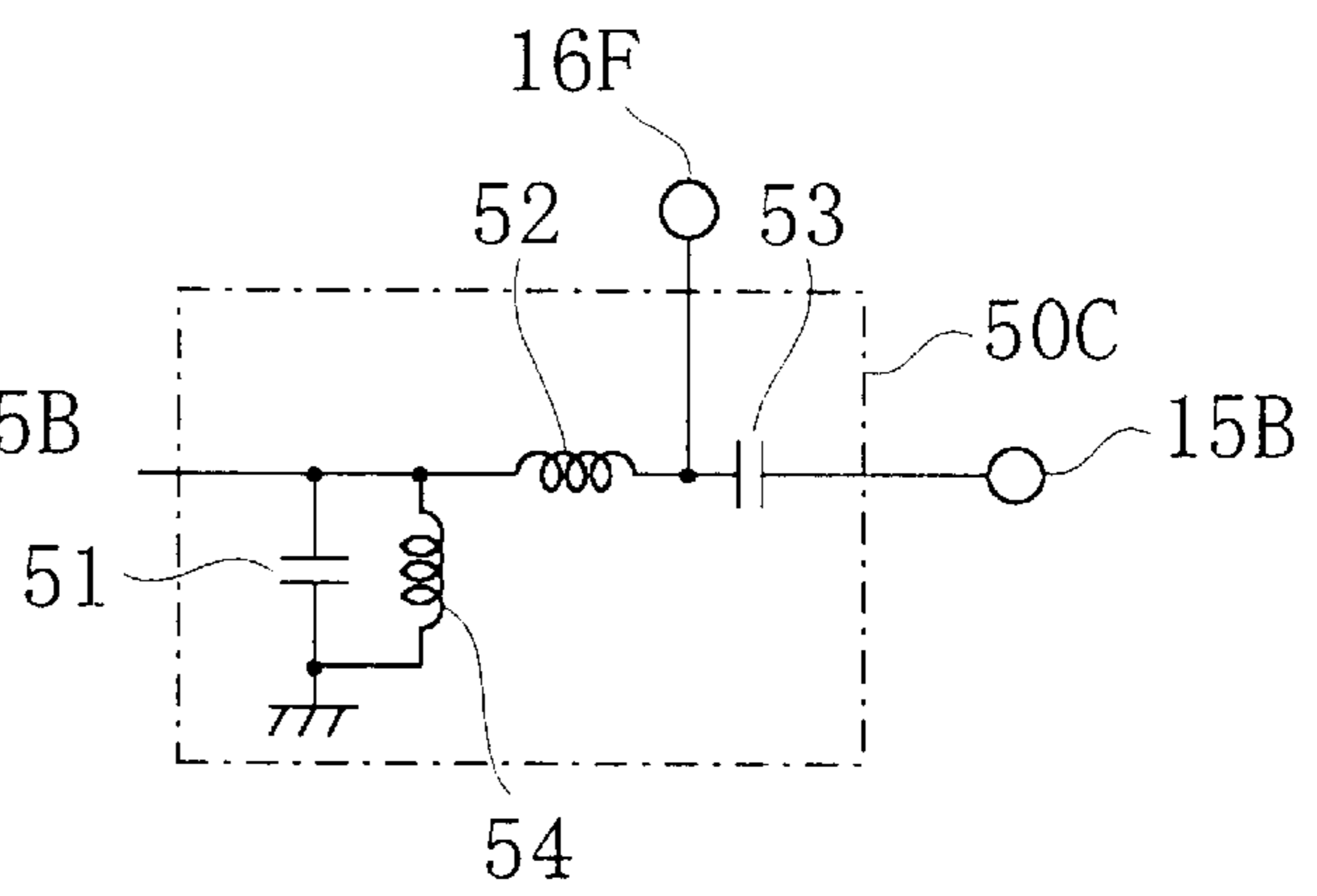


Fig. 6(c)

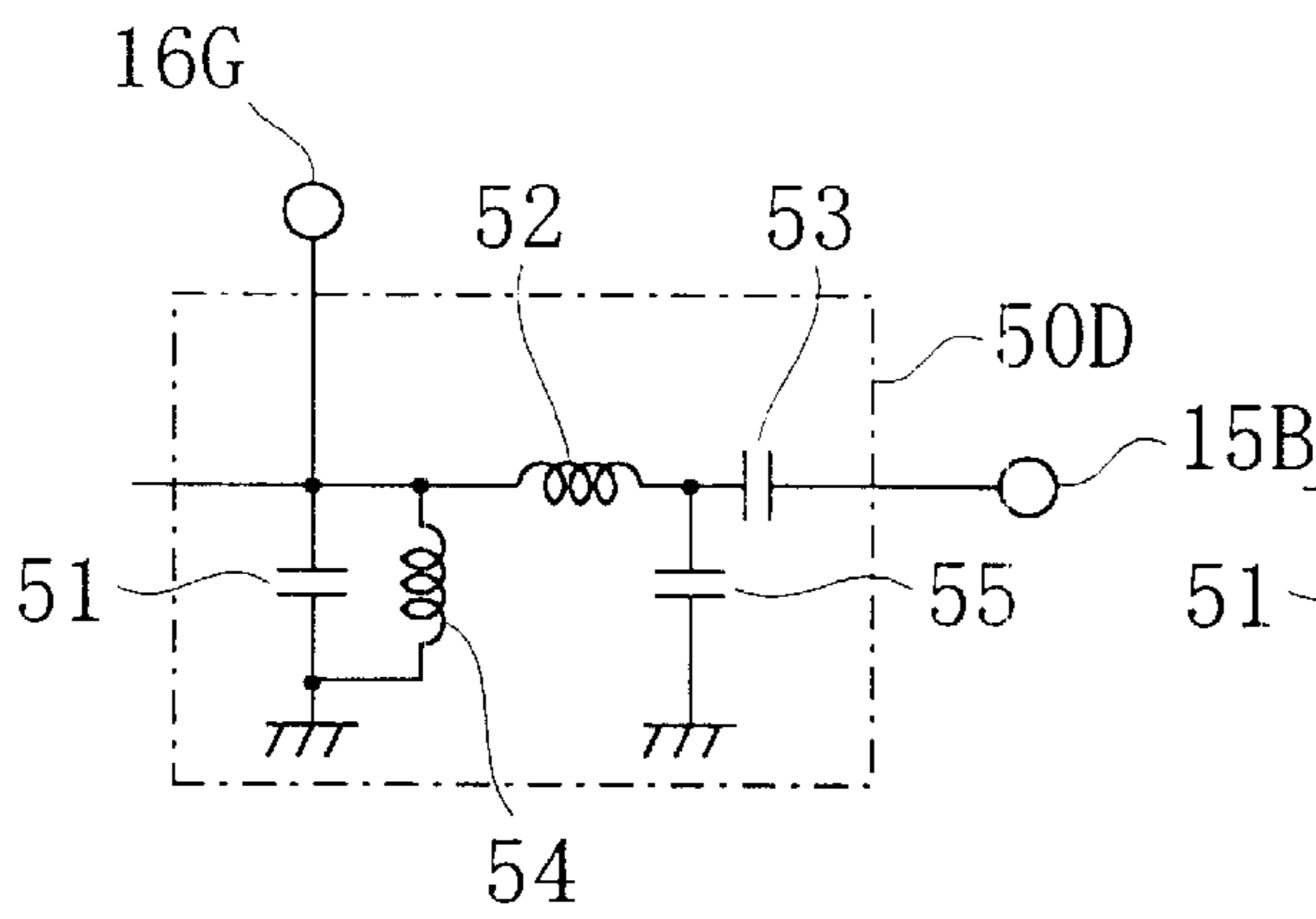


Fig. 6(d)

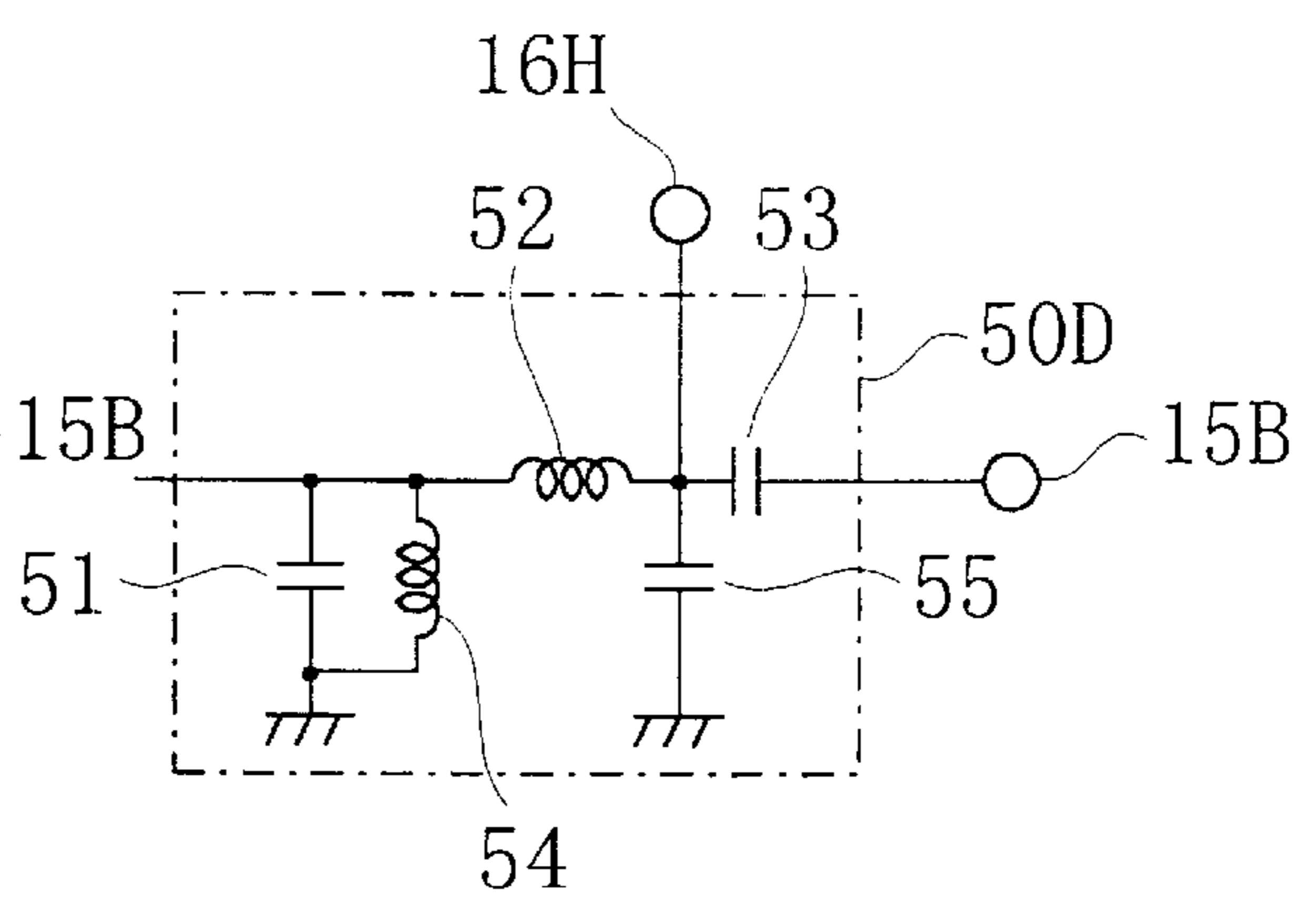


Fig. 7

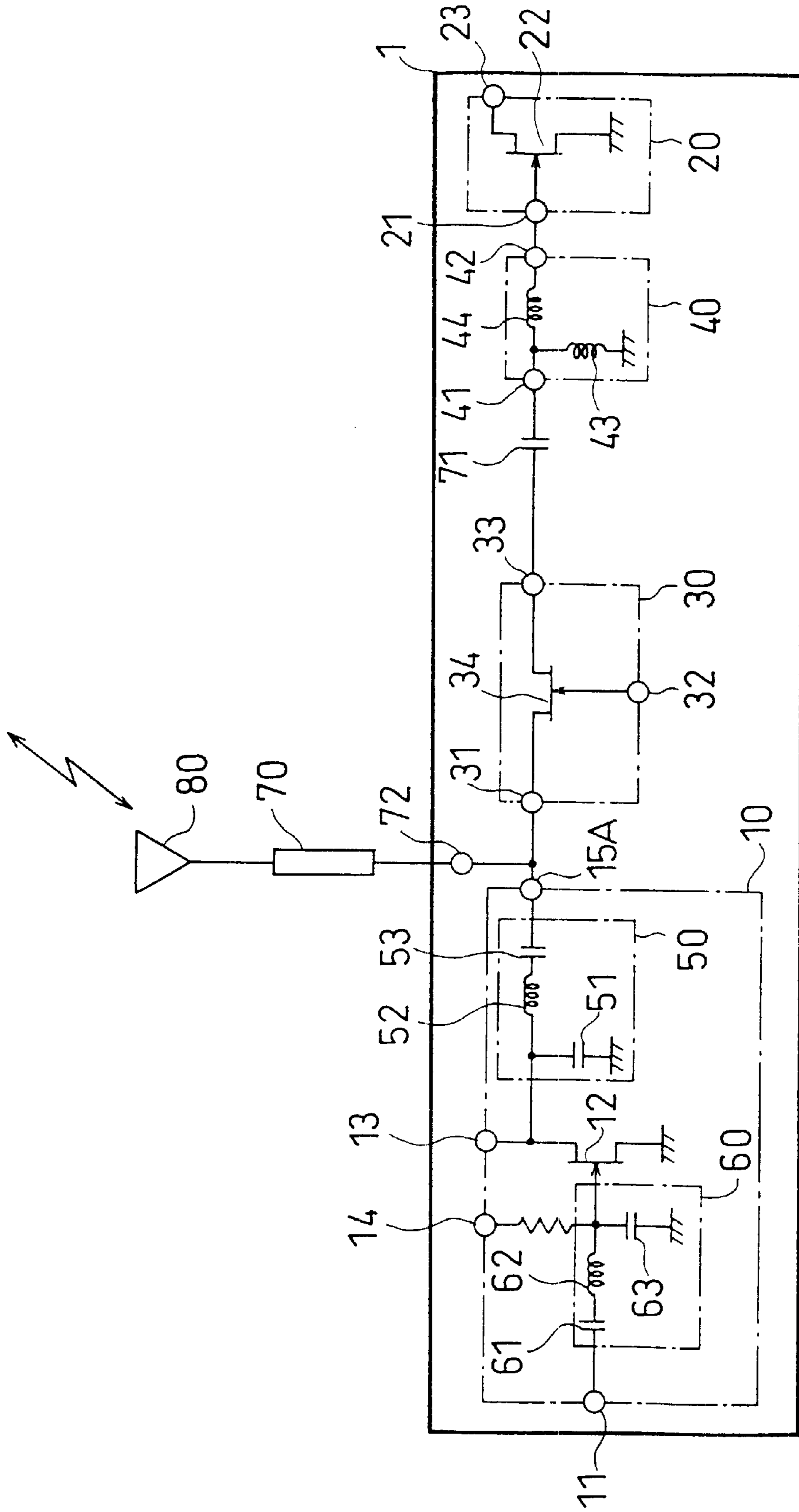




Fig. 8

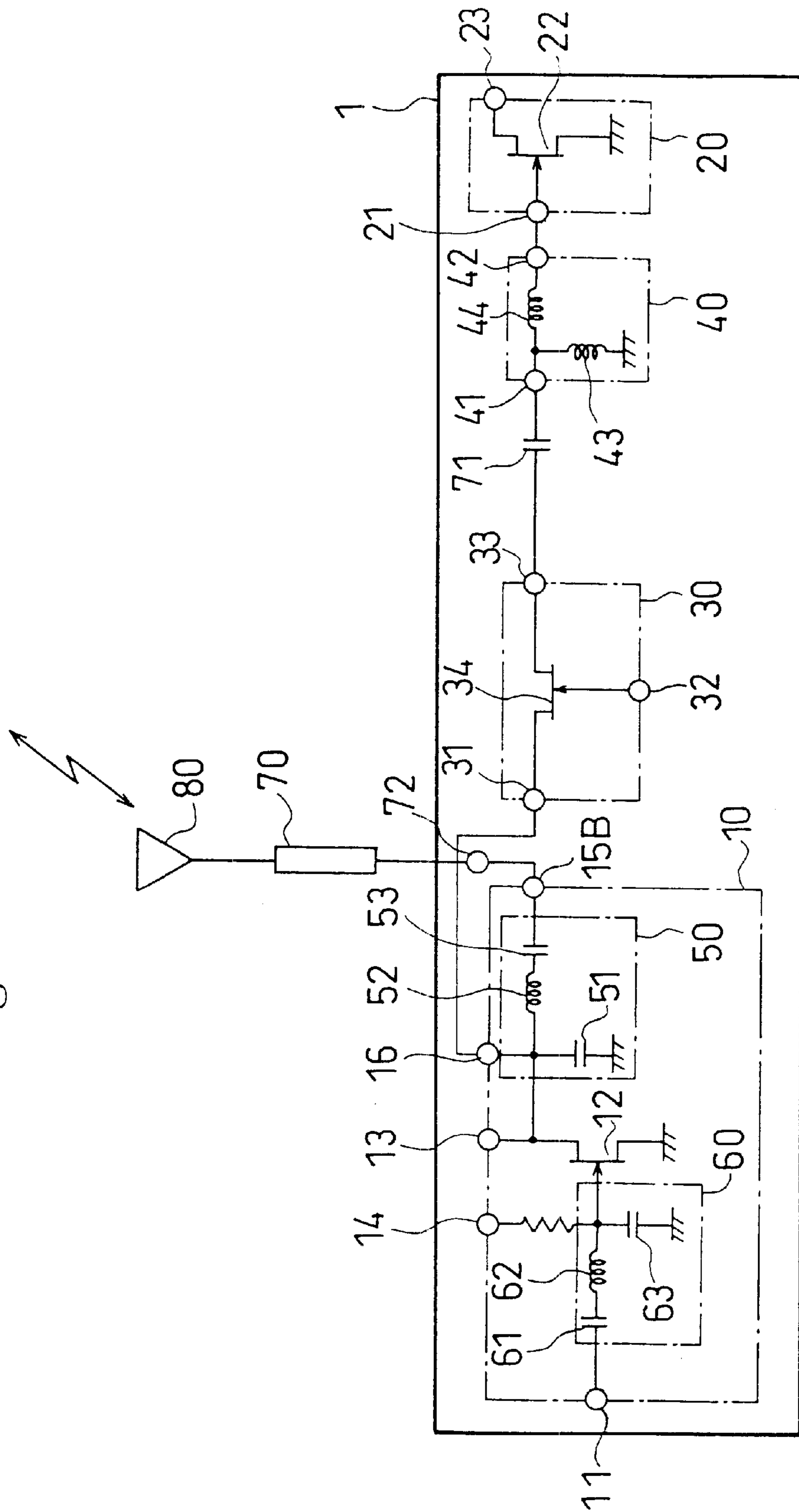


Fig. 9

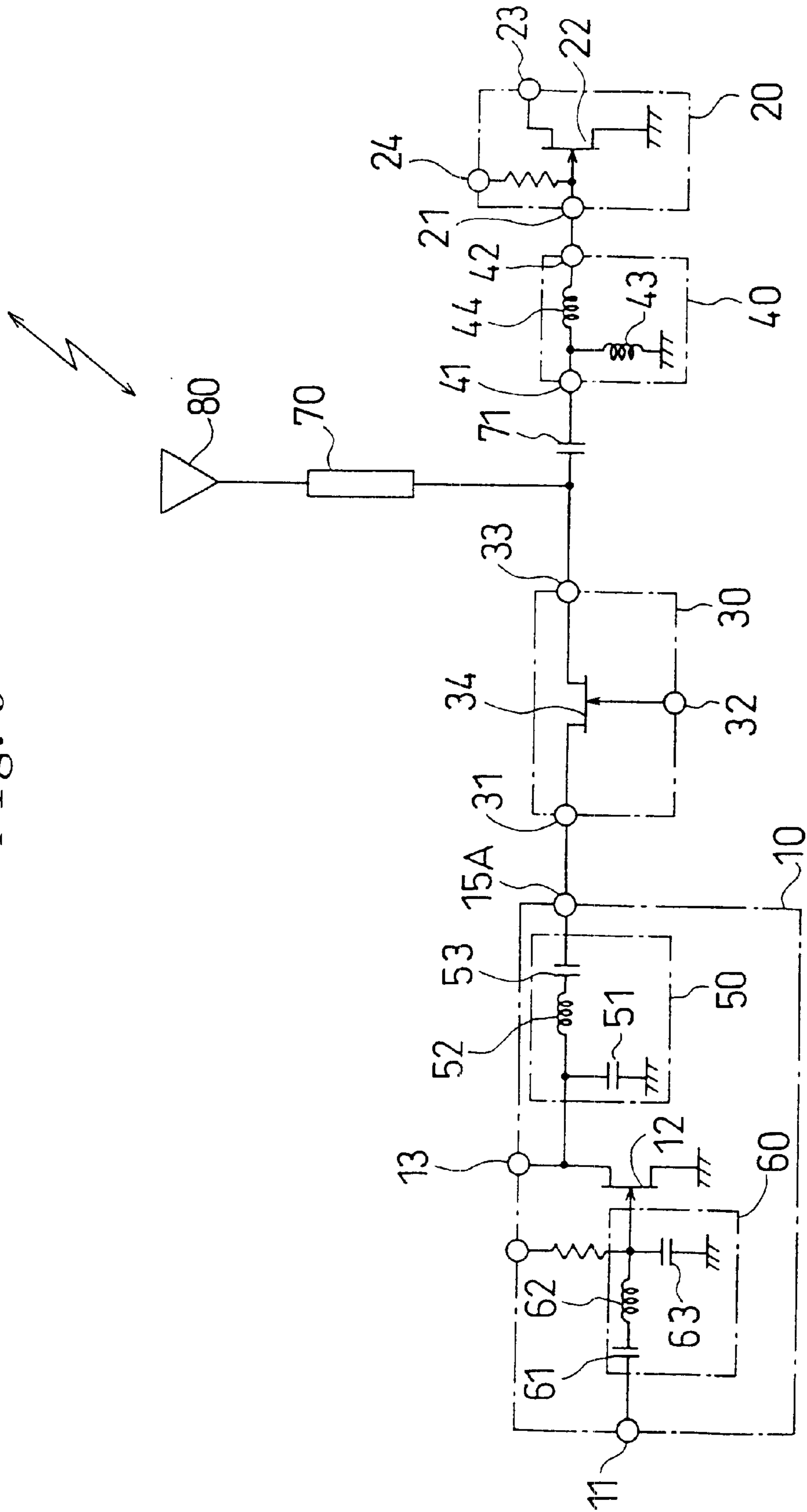


Fig. 10

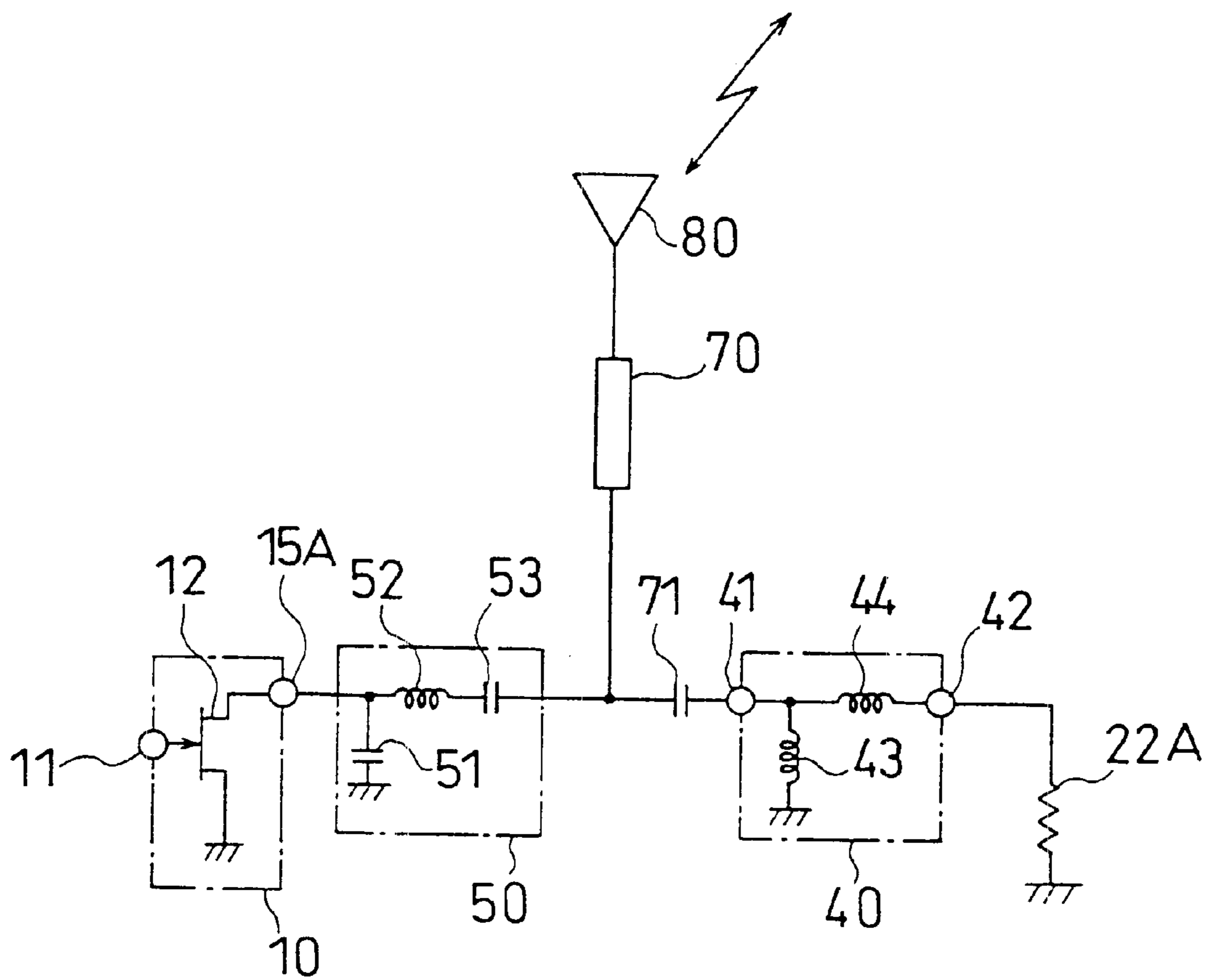
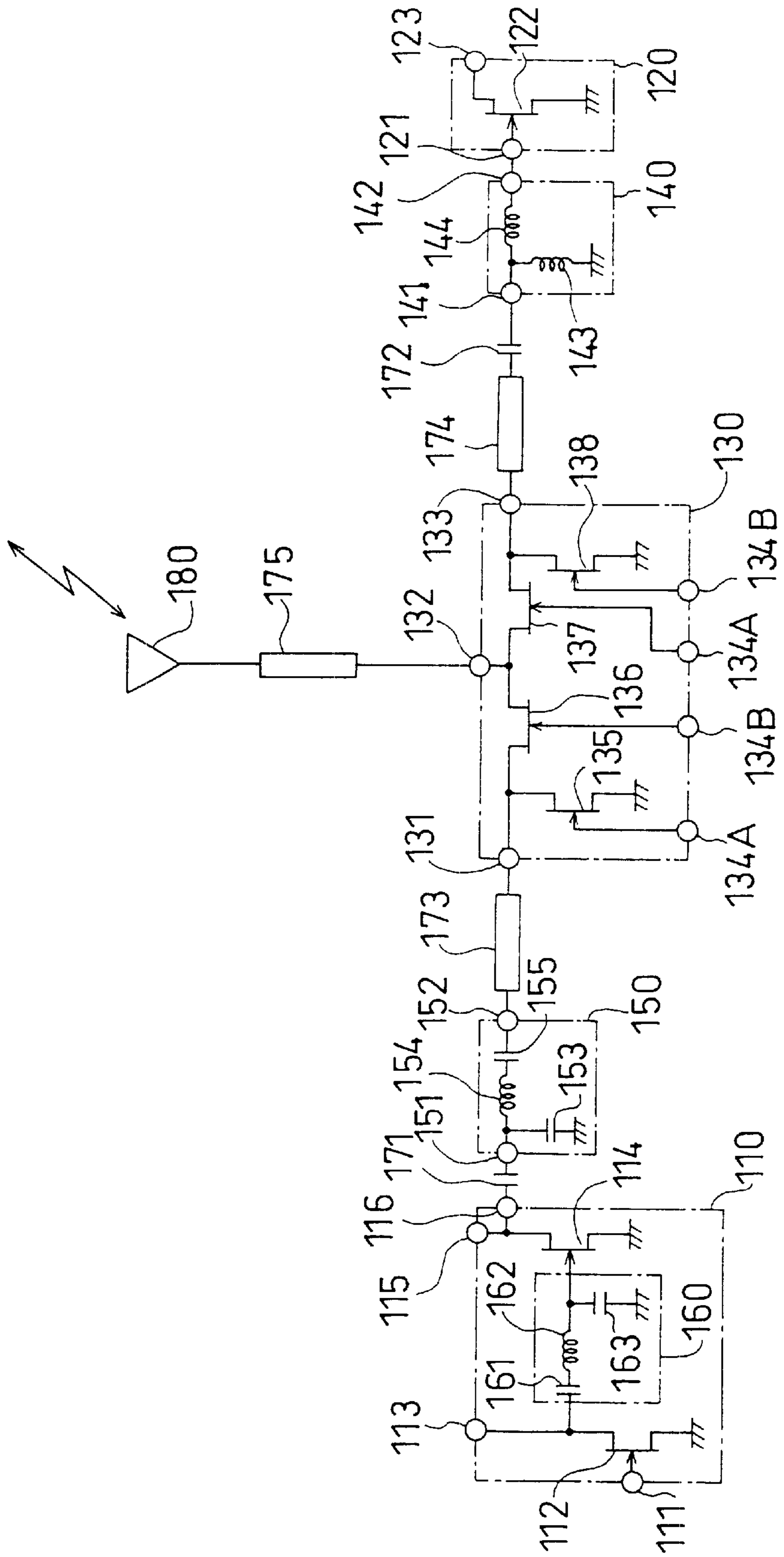


Fig. 11



**TRANSMITTER-RECEIVER CIRCUIT FOR  
RADIO COMMUNICATION AND  
SEMICONDUCTOR INTEGRATED CIRCUIT  
DEVICE**

TECHNICAL FIELD

The present invention relates to a transmitter-receiver circuit and also relates to a semiconductor integrated circuit device including the transmitter-receiver circuit. More particularly, the present invention relates to transmitter-receiver circuit and semiconductor integrated circuit device suitable for a wireless communication unit using the same frequency as both transmission frequency and reception frequency.

BACKGROUND ART

In recent years, size, weight and price of various wireless communication units, e.g., portable cellular phone units for radio communication, have been drastically reduced, and the number of users thereof has been rapidly increasing. In conventional communication systems, a system configuration requiring distinct frequencies for transmission and reception has been adopted so far. On the other hand, in order to satisfy the needs of an even larger number of users, digital implementation has been gradually applied to these units. While two distinct frequencies per line have been required conventionally, such a digital wireless communication unit can perform transmission and reception with the same frequency by dividing transmission and reception in a time-division manner.

Even in such a wireless communication unit utilizing digital implementation, however, various circuits in a wireless circuit section, including a transmitter amplifier, a low-noise receiver amplifier and a transmission/reception mode switch for switching transmission and reception, are still implemented by conventional circuits. Thus, it is an important problem to develop downsized transmitter-receiver circuits and, in particular, semiconductor integrated circuit integrated with these circuits that are suitably applicable to brand-new digital implementation.

Also, a circuit including gallium-arsenide field effect transistors (hereinafter, simply referred to as "GaAs FETs"), having low-voltage, high-efficiency and low-noise operating characteristics and high-isolation characteristics, are often used for a transmitter amplifier, a low-noise receiver amplifier and a transmission/reception mode switch in a transmitter-receiver circuit for a wireless communication unit of a digital type.

Hereinafter, an example of a conventional transmitter-receiver circuit will be described with reference to the drawings.

FIG. 11 illustrates a configuration of a conventional digital transmitter-receiver circuit using FETs. In FIG. 11, **110** denotes a transmitter amplifier for amplifying an input signal to be transmitted and then outputting the amplified signal. **120** denotes a low-noise receiver amplifier for amplifying an input received signal and then outputting the amplified signal. **130** denotes a mode switch for switching transmission state and reception state in a time-division manner. **140** denotes a first matching circuit for matching the impedance of the input received signal with the input impedance of the low-noise receiver amplifier **120**. **150** denotes a second matching circuit for matching the output impedance of the transmitter amplifier **110** with predetermined impedance. **160** denotes a third matching circuit for matching the output impedance of a FET **112** on the first

stage with the input impedance of a FET on the second stage. **171** denotes first coupling capacitance for ac coupling the transmitter amplifier **110** with the second matching circuit **150**. **172** denotes second coupling capacitance for ac coupling the mode switch **130** with the first matching circuit **140**. **173** denotes a first interconnection, having characteristic impedance of **500**, for connecting the mode switch **130** to the second matching circuit **150**. **174** denotes a second interconnection, having characteristic impedance of  $50\Omega$ , for connecting the mode switch **130** to the first matching circuit **140**. **175** denotes a third interconnection, having characteristic impedance of  $50\Omega$ , for connecting the mode switch **130** to an antenna **180** used both for transmission and reception.

In the transmitter amplifier **110** shown in FIG. 11, **111** denotes an input terminal, through which a signal to be transmitted is input. **112** denotes a FET on the first stage, of which the gate electrode is provided with the input signal to be transmitted and the source is grounded. **113** denotes a first power supply terminal connected to the drain electrode of the FET **112** on the first stage. **114** denotes a FET on the second stage, of which the gate electrode is provided with the signal to be transmitted via the third matching circuit **160** and the source is grounded. **115** denotes a second power supply terminal connected to the drain electrode of the FET **114** on the second stage. **116** denotes an output terminal connected to the drain electrode of the FET **114** on the second stage.

In the low-noise receiver amplifier **120** shown in FIG. 11, **121** denotes an input terminal, through which a received signal is input via the first matching circuit **140**. **122** denotes a low-noise FET, of which the gate electrode is provided with the received signal and the source is grounded. **123** denotes an output terminal connected to the drain electrode of the low-noise FET **122**.

In the mode switch **130** shown in FIG. 11, **131** denotes an input terminal on the transmission side connected to the second matching circuit **150**. **132** denotes an input/output terminal on the antenna side for outputting a signal to be transmitted, which has been amplified by the transmitter amplifier **110** and then input thereto via the second matching circuit **150** during transmission, to the antenna **180**, and for receiving the received signal that has been received by the antenna **180** during reception. **133** denotes an output terminal on the reception side, through which the received signal input from the input/output terminal **132** on the antenna side is output. **134A** denotes first switch-control-signal input terminals for controlling a first switching FET **135** and a third switching FET **137**. **134B** denotes second switch-control-signal input terminals for controlling a second switching FET **136** and a fourth switching FET **138**.

In the first matching circuit **140** shown in FIG. 11, **141** denotes an input terminal connected to the output terminal **133** on the reception side of the mode switch **130** via the second coupling capacitance **172**. **142** denotes an output terminal connected to the input terminal **121** of the low-noise receiver amplifier **120**. **143** denotes a first inductor, one end of which is connected to the input terminal **141** and the other end of which is grounded, for constituting the first matching circuit **140**. **144** denotes a second inductor, one end of which is connected to the input terminal **141** and the other end of which is connected to the output terminal **142**, for constituting the first matching circuit **140**.

In the second matching circuit **150** shown in FIG. 11, **151** denotes an input terminal connected to the output terminal **116** of the transmitter amplifier via the first coupling capaci-

tance 171. 152 denotes an output terminal connected to the input terminal 131 on the transmission side of the mode switch 130. 153 denotes a first capacitor, one end of which is connected to the input terminal 151 and the other end of which is grounded, for constituting the second matching circuit 150. 154 denotes an inductor, one end of which is connected to the input terminal 151 and the other end of which is connected to a second capacitor 155, for constituting the second matching circuit 150. 155 denotes the second capacitor, one end of which is connected to the inductor 154 and the other end of which is connected to the output terminal 152, for constituting the second matching circuit 150.

In the third matching circuit 160 shown in FIG. 11, 161 denotes a first capacitor, one end of which is connected to the drain electrode of the FET 112 on the first stage in the transmitter amplifier 110 and the other end of which is connected to an inductor 162, for constituting the third matching circuit 160. 162 denotes the inductor, one end of which is connected to the first capacitor 161 and the other end of which is connected to the gate electrode of the FET 114 on the second stage in the transmitter amplifier 110, for constituting the third matching circuit 160. 163 denotes a second capacitor, one end of which is connected to the inductor 162 and the gate electrode of the FET 114 on the second stage and the other end of which is grounded, for constituting the third matching circuit 160.

Hereinafter, the operation of the transmitter-receiver circuit having the above-described configuration will be described.

First, the operation during reception will be described.

A less intense received signal, input via the antenna 180, passes through the third interconnection 175 having characteristic impedance of  $50\Omega$  and is input to the input/output terminal 132 on the antenna side of the mode switch 130. At this point in time, in the mode switch 130, the first switching FET 135 and the third switching FET 137 have been turned ON responsive to the control signal input through the first switch-control-signal input terminals 134A, while the second switching FET 136 and the fourth switching FET 138 have been turned OFF responsive to the control signal input through the second switch-control-signal input terminals 134B. Thus, the input signal is selectively directed to the low-noise receiver amplifier 120 via the third switching FET 137, which has been turned ON. On the other hand, the circuit section including the transmitter amplifier 110 is electrically isolated from the circuit section including the low-noise receiver amplifier 120, because the second switching FET 136 has been turned OFF. Also, the former circuit section is short-circuited, because the first switching FET 135 has been turned ON.

The signal switched by the third switching FET 137 in the conductive state is output through the output terminal on the reception side of the mode switch 130, passed through the second interconnection 174 having characteristic impedance of  $50\Omega$  and the second coupling capacitance 172 and then input to the first matching circuit 140. Then, impedance matching is performed by the first inductor 143 and the second inductor 144 of the first matching circuit 140. Thereafter, the signal is input to the input terminal 121 of the low-noise receiver amplifier 120. The received signal input to the low-noise receiver amplifier 120 is amplified by the low-noise FET 122 and the amplified signal is output through the output terminal 123.

Next, the operation during transmission will be described.

First, modulated signal to be transmitted is input to the input terminal 131 of the transmitter amplifier 110. Power

amplification on the first stage is performed by the FET 112 on the first stage. Impedance conversion is performed by the third matching circuit 160. Then, the signal is input to the FET 114 on the second stage. The power of the signal is amplified by the FET 114 on the second stage so as to reach predetermined power. The amplified signal to be transmitted is input to the second matching circuit 150 via the first coupling capacitance 171. The characteristic impedance thereof is converted to be  $50\Omega$ . And then the signal is input to the input terminal 131 on the transmission side of the mode switch 130 through the first interconnection 173 having characteristic impedance of  $50\Omega$ .

At this point in time, in the mode switch 130, the second switching FET 136 and the fourth switching FET 138 have been turned ON responsive to the control signal input through the second switch-control-signal input terminals 134B, while the first switching FET 135 and the third switching FET 137 have been turned OFF responsive to the control signal input through the first switch-control-signal input terminals 134A. Thus, the input signal to be transmitted is selectively directed to the antenna 180 via the second switching FET 136, which has been turned ON. On the other hand, the circuit section including the low-noise receiver amplifier 120 is electrically isolated from the circuit section including the transmitter amplifier 110, because the third switching FET 137 has been turned OFF. Also, the former circuit section is short-circuited, because the fourth switching FET 138 has been turned ON.

The amplified signal to be transmitted passes through the second switching FET 136 in the conductive state and the third interconnection 175 having characteristic impedance of  $50\Omega$  and is input to the antenna 180 so as to be output through the antenna 180 as radio waves.

The above-described conventional transmitter-receiver circuit, however, had a problem in that the loss of a signal passing through the mode switch 130 is large. In particular, the loss of a signal to be transmitted becomes an issue because such a signal requires high power. Thus, it is necessary to improve the performance of a through switching FET on the transmission side. In general, in order to reduce the pass loss, a switching FET having a large gate length is required. In addition, if switching FETs of such a large size are integrated, then the chip area is increased to such a degree that the area occupied by the mode switch 130 becomes substantially equal to the area of the transmitter amplifier 110. Thus, problems are present in that downsizing and cost-reduction thereof are hard to realize.

The present invention can solve the above-described conventional problems all at once, and has objects of reducing the power consumption by eliminating the pass loss caused by the mode switch on the signal to be transmitted and downsizing a wireless communication unit by reducing the area occupied by the mode switch in the transmitter-receiver circuit.

#### DISCLOSURE OF THE INVENTION

In order to accomplish the above-described objects, the present invention connects a transmitter amplifier to an antenna without interposing any mode switch therebetween by matching the inputs to a receiver amplifier while using, in combination, the output impedance of the transmitter amplifier during the OFF state and the output impedance to the receiver amplifier.

A transmitter-receiver circuit for a wireless communication unit according to the present invention includes: a transmitter amplifier for amplifying and outputting an input

signal to be transmitted; a receiver amplifier for amplifying and outputting an input received signal; and a mode switch, connected to an antenna used for both transmission and reception, for switching a transmission state where the signal to be transmitted, which has been output by the transmitter amplifier, is output to the antenna and a reception state where the received signal, to be input to the receiver amplifier, is input through the antenna. The transmitter amplifier includes: an amplifying FET, having a gate electrode connected to an input terminal of the signal to be transmitted, a drain electrode connected to a power supply terminal and a source electrode grounded; a matching circuit, connected between the drain electrode of the FET and the antenna, for matching output impedance of the FET with impedance on the antenna side; a control terminal connected to the gate electrode of the FET; and an output terminal directly connected to the antenna without passing through the mode switch.

In the transmitter-receiver circuit for a wireless communication unit, since the output terminal of the transmitter amplifier is directly connected to the antenna without passing through the mode switch during transmission, the pass loss, ordinarily caused by a switch on a signal to be transmitted, can be eliminated. As a result, the power consumption can be reduced. On the other hand, during reception, since a control terminal connected to the gate electrode of the FET of the transmitter amplifier is provided, the circuit section on the transmission side is short-circuited by applying a predetermined voltage to the gate electrode and using the FET having the grounded source as resistance. As a result, a mode switch on the transmission side, which has conventionally been required, is no longer necessary. In other words, a mode switch on the reception side may be constituted by only one switching device, and thus the area occupied by the mode switch in the entire circuit can be reduced. As a result, the overall size of the transmitter-receiver circuit can be reduced.

Another transmitter-receiver circuit for a wireless communication unit according to the present invention includes: a transmitter amplifier for amplifying and outputting an input signal to be transmitted; a receiver amplifier for amplifying and outputting an input received signal; and a mode switch, connected to an antenna used for both transmission and reception, for switching a transmission state where the signal to be transmitted, which has been output by the transmitter amplifier, is output to the antenna and a reception state where the received signal, to be input to the receiver amplifier, is input through the antenna. The transmitter amplifier includes: an amplifying FET, having a gate electrode connected to an input terminal of the signal to be transmitted, a drain electrode connected to a power supply terminal and a source electrode grounded; a matching circuit, connected between the drain electrode of the FET and the antenna, for matching output impedance of the FET with impedance on the antenna side; a control terminal connected to the gate electrode of the FET; and an output terminal directly connected to the antenna without passing through the mode switch. The input terminal on the antenna side of the mode switch is connected to a terminal of the matching circuit, which is different from the output terminal of the signal to be transmitted of the matching circuit.

In the transmitter-receiver circuit for a wireless communication unit, since the output terminal of the transmitter amplifier is directly connected to the antenna without passing through the mode switch during transmission, the pass loss, ordinarily caused by a switch on a signal to be transmitted, can be eliminated. As a result, the power

consumption can be reduced. On the other hand, during reception, since a control terminal connected to the gate electrode of the FET of the transmitter amplifier is provided, the circuit section on the transmission side is short-circuited by applying a predetermined voltage to the gate electrode and using the FET having the grounded source as resistance. As a result, a mode switch on the transmission side, which has conventionally been required, is no longer necessary. In other words, a mode switch on the reception side may be constituted by only one switching device, and thus the area occupied by the mode switch in the entire circuit can be reduced. As a result, the overall size of the transmitter-receiver circuit can be reduced. Moreover, where a receiving matching circuit for matching the impedance of the received signal with the input impedance of the receiver amplifier is provided between the mode switch and the receiver amplifier, a terminal allowing for optimization of the circuit constant of the receiving matching circuit can be selected. As a result, since the design flexibility of the receiving matching circuit can be increased, the size of the receiving matching circuit can be reduced.

A semiconductor integrated circuit device according to the present invention, includes: a semiconductor substrate; a transmitter amplifier, formed on the semiconductor substrate, for amplifying and outputting an input signal to be transmitted; a receiver amplifier, formed on the semiconductor substrate, for amplifying and outputting an input received signal; and a mode switch, formed on the semiconductor substrate and connected to an input/output terminal on an antenna side used for both transmission and reception, for switching a transmission state where the signal to be transmitted, which has been output by the transmitter amplifier, is output to the input/output terminal on the antenna side and a reception state where the received signal, to be input to the receiver amplifier, is input through the input/output terminal on the antenna side. The transmitter amplifier includes: an amplifying FET, having a gate electrode connected to an input terminal of the signal to be transmitted, a drain electrode connected to a power supply terminal and a source electrode grounded; a matching circuit, connected between the drain electrode of the FET and the input/output terminal on the antenna side, for matching output impedance of the FET with impedance on the antenna side; a control terminal connected to the gate electrode of the FET; and an output terminal directly connected to the input/output terminal on the antenna side without passing through the mode switch.

In the semiconductor integrated circuit device, since the output terminal of the transmitter amplifier is directly connected to the input/output terminal on the antenna side without passing through the mode switch during transmission, the pass loss, ordinarily caused by a switch on a signal to be transmitted, can be eliminated. As a result, the power consumption can be reduced. On the other hand, during reception, since a control terminal connected to the gate electrode of the FET of the transmitter amplifier is provided, the circuit section on the transmission side is short-circuited by applying a predetermined voltage to the gate electrode and using the FET as resistance. As a result, a mode switch on the reception side may be constituted by only one switching device, and thus the area occupied by the mode switch in the entire circuit can be reduced. Consequently, features advantageous for high integration can be attained and the device can be downsized.

Another semiconductor integrated circuit device according to the present invention includes: a semiconductor substrate; a transmitter amplifier, formed on the semicon-

ductor substrate, for amplifying and outputting an input signal to be transmitted; a receiver amplifier, formed on the semiconductor substrate, for amplifying and outputting an input received signal; and a mode switch, formed on the semiconductor substrate and connected to an input/output terminal on an antenna side used for both transmission and reception, for switching a transmission state where the signal to be transmitted, which has been output by the transmitter amplifier, is output to the input/output terminal on the antenna side and a reception state where the received signal, to be input to the receiver amplifier, is input through the input/output terminal on the antenna side. The transmitter amplifier includes: an amplifying FET, having a gate electrode connected to an input terminal of the signal to be transmitted, a drain electrode connected to a power supply terminal and a source electrode grounded; a matching circuit, connected between the drain electrode of the FET and the input/output terminal on the antenna side, for matching output impedance of the FET with impedance on the antenna side; a control terminal connected to the gate electrode of the FET; and an output terminal directly connected to the input/output terminal on the antenna side without passing through the mode switch. The input terminal on the antenna side of the mode switch is connected to a terminal of the matching circuit, which is different from the output terminal of the signal to be transmitted of the matching circuit.

In the semiconductor integrated circuit device, since the output terminal of the transmitter amplifier is directly connected to the input/output terminal on the antenna side without passing through the mode switch during transmission, the pass loss, ordinarily caused by a switch on a signal to be transmitted, can be eliminated. As a result, the power consumption can be reduced. On the other hand, during reception, since a control terminal connected to the gate electrode of the FET of the transmitter amplifier is provided, the circuit section on the transmission side is short-circuited by applying a predetermined voltage to the gate electrode and using the FET as resistance. As a result, a mode switch on the transmission side is no longer necessary. In other words, a mode switch on the reception side may be constituted by only one switching device, and thus the area occupied by the mode switch in the entire circuit can be reduced. Moreover, where a receiving matching circuit for matching the impedance of the received signal with the input impedance of the receiver amplifier is provided between the mode switch and the receiver amplifier, a terminal allowing for optimization of the circuit constant of the receiving matching circuit can be selected. As a result, since the design flexibility of the receiving matching circuit can be increased, the size of the receiving matching circuit can be reduced. Consequently, the size of the device can be further reduced.

#### BRIEF DESCRIPTION OF THE DRAWINGS

FIG. 1 is a circuit diagram of a transmitter-receiver circuit for a wireless communication unit according to the first embodiment of the present invention.

FIG. 2 is an equivalent circuit diagram where the transmitter-receiver circuit for a wireless communication unit according to the first embodiment of the present invention performs receiving operation.

FIG. 3 is a circuit diagram of a transmitter-receiver circuit for a wireless communication unit according to the second embodiment of the present invention.

FIG. 4 is an equivalent circuit diagram where the transmitter-receiver circuit for a wireless communication

unit according to the second embodiment of the present invention performs receiving operation.

FIGS. 5(a) through 5(d) are circuit diagrams illustrating variations of a second matching circuit and an output terminal of a received signal in the transmitter-receiver circuit for a wireless communication unit according to the second embodiment of the present invention.

FIGS. 6(a) through 6(d) are circuit diagrams illustrating variations of the second matching circuit and the output terminal of the received signal in the transmitter-receiver circuit for a wireless communication unit according to the second embodiment of the present invention.

FIG. 7 is a circuit diagram of a transmitter-receiver circuit where GaAs FETs are used for a semiconductor integrated circuit device according to the third embodiment of the present invention.

FIG. 8 is a circuit diagram of a transmitter-receiver circuit where GaAs FETs are used for a semiconductor integrated circuit device according to the fourth embodiment of the present invention.

FIG. 9 is a circuit diagram of a transmitter-receiver circuit for a wireless communication unit according to the fifth embodiment of the present invention.

FIG. 10 is an equivalent circuit diagram where the transmitter-receiver circuit for a wireless communication unit according to the fifth embodiment of the present invention performs transmitting operation.

FIG. 11 is a circuit diagram of a conventional transmitter-receiver circuit of a digital type using FETs.

#### BEST MODE FOR CARRYING OUT THE INVENTION

##### First Embodiment

Hereinafter, the first embodiment of the present invention will be described with reference to the drawings.

FIG. 1 is a circuit diagram of a transmitter-receiver circuit for a wireless communication unit according to the first embodiment of the present invention. In FIG. 1, **10** denotes a transmitter amplifier for amplifying an input signal to be transmitted and then outputting the amplified signal. **20** denotes a low-noise receiver amplifier for amplifying an input received signal and then outputting the amplified signal. **30** denotes a mode switch for switching transmission state and reception state in a time-division manner. **40** denotes a first matching circuit for matching the impedance of the input received signal with the input impedance of the low-noise receiver amplifier **20**. **50** denotes a second matching circuit for matching the output impedance of the transmitter amplifier **10** with predetermined impedance. **60** denotes a third matching circuit for matching the impedance of the input signal to be transmitted with the input impedance of a high-power FET **12** of the transmitter amplifier **10**. **70** denotes an interconnection, having characteristic impedance of  $50\Omega$ , for connecting the mode switch **30**, the transmitter amplifier **10** and an antenna **80** used for both transmission and reception with each other. **71** denotes coupling capacitance for ac coupling the mode switch **30** to the first matching circuit **40**.

In the transmitter amplifier **10** shown in FIG. 1, **11** denotes an input terminal, through which a signal to be transmitted is input. **12** denotes a high-power FET, of which the gate electrode is provided with the input signal to be transmitted via the third matching circuit **60** and the source is grounded. **13** denotes a power supply terminal connected to the drain electrode of the high-power FET **12**. **14** denotes a control terminal connected to the gate electrode of the high-power



FET **12** via resistance. **15A** denotes an output terminal connected to the antenna **80** through an interconnection **70** having characteristic impedance of **500** and to an input terminal **31** of the mode switch **30**.

In the low-noise receiver amplifier **20** shown in FIG. **11**, **21** denotes an input terminal, through which a received signal is input via the first matching circuit **40**. **22** denotes a low-noise FET, of which the gate electrode is provided with the received signal and the source is grounded. **23** denotes an output terminal connected to the drain electrode of the low-noise FET **22**.

In the mode switch **30** shown in FIG. **1**, **31** denotes an input terminal connected to the antenna **80** through the interconnection **70** having characteristic impedance of  $50\Omega$  and to the output terminal **15A** of the transmitter amplifier **10**. **32** denotes a switch-control-signal input terminal for controlling a switching FET **34**. **33** denotes an output terminal, through which the received signal, input through the antenna **80**, is output.

In the first matching circuit **40** shown in FIG. **1**, **41** denotes an input terminal connected to the output terminal **33** of the mode switch **30** via the coupling capacitance **71**. **42** denotes an output terminal connected to the input terminal **21** of the low-noise receiver amplifier **20**. **43** denotes a first inductor, one end of which is connected to the input terminal **41** and the other end of which is grounded, for constituting the first matching circuit **40**. **44** denotes a second inductor, one end of which is connected to the input terminal **41** and the other end of which is connected to the output terminal **42**, for constituting the first matching circuit **40**.

In the second matching circuit **50** shown in FIG. **1**, **51** denotes a first capacitor, one end of which is connected to the drain electrode of the high-power FET **12** and the other end of which is grounded, for constituting the second matching circuit **50**. **52** denotes an inductor, one end of which is connected to the drain electrode of the high-power FET **12** and the other end of which is connected to a second capacitor **53**, for constituting the second matching circuit **50**. **53** denotes a second capacitor, one end of which is connected to the inductor **52** and the other end of which is connected to the output terminal **15A**, for constituting the second matching circuit **50**.

In the third matching circuit **60** shown in FIG. **1**, **61** denotes a first capacitor, one end of which is connected to the input terminal **11** of the transmitter amplifier **10** and the other end of which is connected to an inductor **62**, for constituting the third matching circuit. **62** denotes the inductor, one end of which is connected to the first capacitor **61** and the other end of which is connected to the gate electrode of the high-power FET **12** of the transmitter amplifier **10**, for constituting the third matching circuit **60**. **63** denotes a second capacitor, one end of which is connected to the inductor **62** and the gate electrode of the high-power FET **12** and the other end of which is grounded, for constituting the third matching circuit.

In this embodiment, the FETs constituting the transmitter amplifier **10**, the low-noise receiver amplifier **20** and the mode switch **30** are assumed to be GaAs FETs or silicon MOSFETs.

Hereinafter, the operation of the transmitter-receiver circuit having the above-described configuration will be described with reference to FIGS. **1** and **2**.

FIG. **2** is an equivalent circuit diagram where the transmitter-receiver circuit for a wireless communication unit according to the first embodiment of the present invention performs receiving operation. In FIG. **2**, the same

components as those of the transmitter-receiver circuit shown in FIG. **1** are identified by the same reference numerals and the description thereof will be omitted herein.

First, the operation thereof during reception will be described.

As shown in FIG. **1**, a less intense received signal, which has been input through the antenna **80**, passes-through the interconnection **70** having characteristic impedance of  $50\Omega$  and is input to the mode switch **30**.

In the mode switch **30**, the switching FET **34** has been turned ON responsive to the control signal input through the switch-control-signal input terminal **32**. Thus, the input received signal is next passed through the switching FET **34**, the output terminal **33** of the mode switch **30** and the coupling capacitance **71** so as to be input to the first matching circuit **40**.

Subsequently, the impedance of the input received signal is matched with the input impedance of the low-noise receiver amplifier **20**. Thereafter, the signal is input to the input terminal **21** of the low-noise receiver amplifier **20**. At this point in time, by turning ON the high-power FET **12** upon the application of a control voltage to the control terminal **14** of the high-power FET **12** in the transmitter amplifier **10**, the high-power FET **12** can be equivalent to pure resistance **12A** as shown in FIG. **2**. Thus, the circuit section on the transmission can be short-circuited during reception. Accordingly, the input impedance of the low-noise receiver amplifier **20** can be matched by the first inductor **43** and the second inductor **44** constituting the first matching circuit **40** and the inductor **52** constituting the second matching circuit **50**.

Next, the received signal input to the low-noise receiver amplifier **20** is amplified by the low-noise FET **22** and then output through the output terminal **23** of the low-noise receiver amplifier **20**.

It is noted that, if the transmitter amplifier **10** performs multiple-stage amplification using a plurality of FETs, the control terminal **14** may be provided for the FET on the last amplification stage.

Next, the operation thereof during transmission will be described with reference to FIG. **1**.

First, a signal to be transmitted, which has been modulated and amplified to reach a predetermined signal level, is input to the input terminal **11** of the transmitter amplifier **10**.

Then, after the impedance of the input signal to be transmitted is matched by the third matching circuit **60** with the input impedance of the high-power FET **12**, the input signal to be transmitted is amplified by the high-power FET **12** to gain predetermined power.

Subsequently, after having been subjected to the impedance conversion by the second matching circuit **50**, the amplified signal to be transmitted is passed through the interconnection **70** having characteristic impedance of  $50\Omega$ , input to the antenna **80** and then output by the antenna **80** as radio waves. Since the switching FET **34** is turned OFF in the mode switch **30**, the circuit section on the reception side is isolated from the antenna **80** and the transmitter amplifier **10**.

This embodiment is characterized in that the transmitter amplifier **10** can be connected to the antenna **80** without interposing any switch therebetween by matching the inputs to the low-noise receiver amplifier **20** using the output impedance of the transmitter amplifier **10** during the OFF state and the output impedance of the first matching circuit **40** to the low-noise receiver amplifier **20**. Thus, since the switch for transmission need not be used, the pass loss caused by a switching device on the output signal of the

transmitter amplifier **10** can be eliminated. As a result, low power consumption is realized during transmission.

In addition, since only one switching FET is necessary, the mode switch can have a reduced area and can be integrated more highly.

The value of resistance where the control terminal **14** of the high-power FET **12** is used as having been turned ON by applying a voltage to the control terminal **14** during the transmission OFF state is equal to or lower than  $1\Omega$ , which is the ON resistance of a generally used FET. Thus, the influence of the resistance on the input matching of the low-noise receiver amplifier **20** is negligible.

#### Second Embodiment

Hereinafter, the second embodiment of the present invention will be described with reference to the drawings.

FIG. **3** is a circuit diagram of a transmitter-receiver circuit for a wireless communication unit according to the second embodiment of the present invention. In FIG. **3**, **10** denotes a transmitter amplifier for amplifying an input signal to be transmitted and then outputting the amplified signal. **20** denotes a low-noise receiver amplifier for amplifying an input received signal and then outputting the amplified signal. **30** denotes a mode switch for switching transmission state and reception state in a time-division manner. **40** denotes a first matching circuit for matching the impedance of the input received signal with the input impedance of the low-noise receiver amplifier **20**. **50** denotes a second matching circuit for matching the output impedance of the transmitter amplifier **10** with predetermined impedance. **60** denotes a third matching circuit for matching the impedance of the input signal to be transmitted with the input impedance of a high-power FET **12** of the transmitter amplifier **10**. **70** denotes an interconnection, having characteristic impedance of  $50\Omega$ , for connecting a terminal **15B** functioning as output terminal for transmission and input terminal for reception of the transmitter amplifier **10** to the antenna **80** used for both transmission and reception. **71** denotes coupling capacitance for ac coupling the mode switch **30** to the first matching circuit **40**. In FIG. **3**, the same components as those of the circuits shown in FIG. **1** are identified by the same reference numerals and the description thereof will be omitted herein.

This embodiment is different from the first embodiment in that the input terminal **31** of the mode switch **30** is connected not to the terminal **15B** functioning as output terminal for transmission and input terminal for reception of the transmitter amplifier **10**, but to an output terminal **16** of the received signal. The output terminal **16** is used in common both as a terminal of the drain electrode of the high-power FET **12** and as a non-grounded terminal of the first capacitor **51** in the second matching circuit **50**.

Hereinafter, the operation of the transmitter-receiver circuit having the above-described configuration will be described with reference to FIGS. **3** and **4**.

The operation thereof during transmission is the same as that of the transmitter-receiver circuit described in the first embodiment, and thus the description thereof will be omitted herein. Only the operation thereof during reception will be described hereinafter.

FIG. **4** is an equivalent circuit diagram where the transmitter-receiver circuit for a wireless communication unit according to the second embodiment performs receiving operation.

First, as shown in FIG. **3**, a less intense received signal, which has been input through the antenna **80**, passes through the interconnection **70** having characteristic impedance of  $50\Omega$ , the terminal **15B** functioning as output terminal for

transmission and input terminal for reception of the transmitter amplifier **10** and the second matching circuit **50**, and then is input to the mode switch **30**.

In the mode switch **30**, the switching FET **34** has been turned ON responsive to the control signal input through the switch-control-signal input terminal **32**. Thus, the input received signal is next passed through the switching FET **34**, the output terminal **33** of the mode switch **30** and the coupling capacitance **71** so as to be input to the first matching circuit **40**.

Subsequently, the impedance of the input received signal is matched with the input impedance of the low-noise receiver amplifier **20** by the first matching circuit **40**. Thereafter, the signal is input to the input terminal **21** of the low-noise receiver amplifier **20**. At this point in time, by turning ON the high-power FET **12** upon the application of a control voltage to the control terminal **14** of the high-power FET **12** in the transmitter amplifier **10**, the high-power FET **12** can be equivalent to pure resistance **12A** as shown in FIG. **4**. Thus, the circuit section on the transmission side can be short-circuited during reception. Accordingly, the input impedance of the low-noise receiver amplifier **20** can be matched by the first inductor **43** and the second inductor **44** constituting the first matching circuit **40** and the inductor **52** constituting the second matching circuit **50**.

Next, the received signal input to the low-noise receiver amplifier **20** is amplified by the low-noise FET **22** and then output through the output terminal **23** of the low-noise receiver amplifier **20**.

It is noted that, if the transmitter amplifier **10** performs multiple-stage amplification using a plurality of FETs, the control terminal **14** may be provided for the FET on the last amplification stage.

As can be understood, in this second embodiment, the resulting number of devices can be reduced, for example, by using the inductor **43** required for the first matching circuit **40** simultaneously as the inductor **52** in the second matching circuit **50** as shown in FIG. **4**. As a result, the size of the first matching circuit **40** can be reduced.

That is to say, during reception, there is no problem if only impedance matching is realized between the antenna **80** and the low-noise receiver amplifier **20** by using the devices of the first matching circuit **40** and the second matching circuit. Thus, by comparison to the first embodiment, the design flexibility of the first matching circuit **40** can be increased.

For example, once the first matching circuit **40** is fixed, the first matching circuit **40** itself cannot be changed. However, even in such a case, by providing the output terminal **16** of the received signal at such a position of the second matching circuit **50** as to optimize the impedance matching with the low-noise receiver amplifier **20**, the first matching circuit **40** can also be connected to the output terminal **16** of the received signal. Thus, the number of devices can be reduced simultaneously.

Herein, variations of the second matching circuit **50** and variations of the output terminal of the received signal at respective positions corresponding to the respective variations where impedance matching with the low-noise receiver amplifier **20** is optimized are illustrated in FIGS. **5** and **6**. In the second matching circuit **50** shown in FIG. **5(a)**, the output terminal **16A** of the received signal is connected to the connection point between the inductor **52** and the second capacitor **53**. In the second matching circuit **50A** shown in FIG. **5(b)**, the inductor is divided into two parts **52A** and **52B**, and the output terminal **16B** of the received signal is connected to the drain electrode of a high-power FET **12**

(not shown) and to a non-grounded terminal, i.e., a common terminal of the first capacitor **51**. In the second matching circuit **50A** shown in FIG. **5(c)**, the output terminal **16C** of the received signal is connected to a common terminal of the inductors **52A** and **52B**. In the second matching circuit **50B** shown in FIG. **5(d)**, one terminal of the inductor **52** is grounded and the other end thereof is connected to the drain electrode of the high-power FET **12** and to the non-grounded terminal, i.e., the common terminal of the first capacitor **51**, to which terminal the output terminal **16D** of the received signal is connected. In the second matching circuit **50C** shown in FIG. **6(a)**, a second inductor **54** is newly added to the second matching circuit **50**, one terminal of the second inductor **54** is grounded and the other end thereof is connected to the drain electrode of the high-power FET **12** and to the non grounded terminal, i.e., the common terminal of the first capacitor **51**, to which terminal the output terminal **16E** of the received signal is connected. In the second matching circuit **50C** shown in FIG. **6(b)**, the output terminal **16F** of the received signal is connected to the connection point between the inductor **52** and the second capacitor **53**. In the second matching circuit **50D** shown in FIG. **6(c)**, a third capacitor **55** is newly added to the second matching circuit **50C**, one terminal of the third capacitor **55** is grounded and the other end thereof is connected to the connection point between the inductor **52** and the second capacitor **53**, and the output terminal **16G** of the received signal is connected to the drain electrode of a high-power FET **12** (not shown) and to a non-grounded terminal, i.e., a common terminal of the first capacitor **51**. In the second matching circuit **50D** shown in FIG. **6(d)**, the output terminal **16H** of the received signal is connected to a common connection point among the inductor **52**, the second capacitor **53** and the third capacitor **55**.

#### Third Embodiment

Hereinafter, the third embodiment of the present invention will be described with reference to the drawings.

FIG. **7** is a circuit diagram of a transmitter-receiver circuit where GaAs FETs are used for a semiconductor integrated circuit device according to the third embodiment of the present invention. That is to say, FIG. **7** is a circuit diagram of a device formed by integrating the transmitter-receiver circuit for a wireless communication unit as described in the first embodiment onto a semiconductor substrate.

In FIG. **7**, **10** denotes a transmitter amplifier for amplifying an input signal to be transmitted and then outputting the amplified signal. **20** denotes a low-noise receiver amplifier for amplifying an input received signal and then outputting the amplified signal. **30** denotes a mode switch for switching transmission state and reception state in a time-division manner. **40** denotes a first matching circuit for matching the impedance of the input received signal with the input impedance of the low-noise receiver amplifier **20**. **50** denotes a second matching circuit for matching the output impedance of the transmitter amplifier **10** with predetermined impedance. **60** denotes a third matching circuit for matching the impedance of the input signal to be transmitted with the input impedance of a high-power FET **12** of the transmitter amplifier **10**. **70** denotes an interconnection, having characteristic impedance of  $50\Omega$ , for connecting an input/output terminal **72** on the antenna side to the antenna **80** used for both transmission and reception. **71** denotes coupling capacitance for ac coupling the mode switch **30** to the first matching circuit **40**.

The respective circuits described above, i.e., the transmitter amplifier **10** including the second matching circuit **50** and the third matching circuit **60**, the low-noise receiver

amplifier **20**, the mode switch **30** and the first matching circuit **40**, are formed on a semiconductor substrate

In the transmitter amplifier **10** shown in FIG. **7**, **11** denotes an input terminal, through which a signal to be transmitted is input. **12** denotes a high-power FET, of which the gate electrode is provided with the input signal to be transmitted via the third matching circuit **60** and the source is grounded. **13** denotes a power supply terminal connected to the drain electrode of the high-power FET **12**. **14** denotes a control terminal connected to the gate electrode of the high-power FET **12**. **15A** denotes a terminal functioning as output terminal on the transmission side and input terminal on the reception side, which is connected to the input/output terminal **72** on the antenna side and to the input terminal **31** of the mode switch **30**.

In the low-noise receiver amplifier **20** shown in FIG. **7**, **21** denotes an input terminal of the low-noise receiver amplifier **20**, through which a received signal is input via the first matching circuit **40**. **22** denotes a low-noise FET, of which the gate electrode is provided with the received signal and the source is grounded. **23** denotes an output terminal of the low-noise receiver amplifier **20** connected to the drain electrode of the low-noise FET **22**.

In the mode switch **30** shown in FIG. **7**, **31** denotes an input terminal connected to the antenna **80** through the interconnection **70** having characteristic impedance of  $50\Omega$  and to the output terminal **15** of the transmitter amplifier **10**. **32** denotes a switch-control-signal input terminal for controlling a switching FET. **33** denotes an output terminal, through which the received signal, input through the antenna **80**, is output. **34** denotes a switching FET constituting the mode switch **30**. In FIG. **7**, the same components as those of the respective matching circuits shown in FIG. **1** are identified by the same reference numerals and the description thereof will be omitted herein.

Since the operation of the semiconductor integrated circuit device according to this embodiment is the same as that of the first embodiment, the description thereof will be omitted herein.

In accordance with this embodiment, the transmitter amplifier **10** can be connected to the antenna **80** without interposing any switch therebetween by matching the inputs to the low-noise receiver amplifier **20** while using, in combination, the output impedance of the transmitter amplifier **10** during the OFF state and the output impedance of the first matching circuit **40** to the low-noise receiver amplifier **20**. Thus, since the use of a switch for transmission is no longer necessary, it is possible to eliminate the pass loss that is ordinarily caused by a switching device on the output signal of the transmitter amplifier **10**. As a result, the power consumption can be reduced during transmission.

In addition, since only one switching FET is required, the area occupied by the mode switch on the transmitter-receiver circuit can be narrowed, high integration is enabled. Ultimately, this fact can contribute to downsizing and cost reduction of a wireless communication unit incorporating the semiconductor integrated circuit device according to this embodiment.

In this embodiment, GaAs FETs are used as the FETs constituting the transmitter amplifier **10**, the low-noise receiver amplifier **20** and the mode switch **30**. Alternatively, these FETs may be silicon MOSFETs.

The value of resistance where the control terminal **14** of the high-power FET **12** is used as having been turned ON by applying a voltage to the control terminal **14** during the transmission OFF state is equal to or lower than **10**, which is the ON resistance of a generally used FET. Thus, the

influence of the resistance on the input matching of the low-noise receiver amplifier **20** is negligible.

#### Fourth Embodiment

Hereinafter, the fourth embodiment of the present invention will be described with reference to the drawings.

FIG. **8** is a circuit diagram of a transmitter-receiver circuit where GaAs FETs are used for a semiconductor integrated circuit device according to the fourth embodiment of the present invention. That is to say, FIG. **8** is a circuit diagram of a device formed by integrating the transmitter-receiver circuit for a wireless communication unit as described in the second embodiment onto a semiconductor substrate.

In FIG. **8**, **10** denotes a transmitter amplifier for amplifying an input signal to be transmitted and then outputting the amplified signal. **20** denotes a low-noise receiver amplifier for amplifying an input received signal and then outputting the amplified signal. **30** denotes a mode switch for switching transmission state and reception state in a time-division manner. **40** denotes a first matching circuit for matching the impedance of the input received signal with the input impedance of the low-noise receiver amplifier **20**. **50** denotes a second matching circuit for matching the output impedance of the transmitter amplifier **10** with predetermined impedance. **60** denotes a third matching circuit for matching the impedance of the input signal to be transmitted with the input impedance of a high-power FET **12** of the transmitter amplifier **10**. **70** denotes an interconnection, having characteristic impedance of  $50\Omega$ , for connecting an input/output terminal **72** on the antenna side to the antenna **80** used for both transmission and reception. **71** denotes coupling capacitance for ac coupling the mode switch **30** to the first matching circuit **40**. It is noted that the same components as those of the respective circuits shown in FIG. **3** are identified by the same reference numerals and the description thereof will be omitted herein.

The respective circuits described above, i.e., the transmitter amplifier **10** including the second matching circuit **50** and the third matching circuit **60**, the low-noise receiver amplifier **20**, the mode switch **30** and the first matching circuit **40**, are formed on a semiconductor substrate **1**.

The fourth embodiment is characterized in that the input terminal **31** of the mode switch **30** is not connected to the terminal **15B** functioning as output terminal for transmission and input terminal for reception of the transmitter amplifier **10**, but to the output terminal **16** of the received signal in the second matching circuit **50**.

The operations thereof during reception and transmission are the same as those of the transmitter-receiver circuit as described in the second embodiment. Thus, the description thereof will be omitted herein.

In accordance with the fourth embodiment, by turning ON the high-power FET **12** upon the application of a control voltage to the control terminal **14** of the high-power FET **12** in the transmitter amplifier **10** shown in FIG. **8** and by using the high-power FET **12** as pure resistance **12A**, the circuit section on the transmission side can be short-circuited and isolated during reception.

Thus, the resulting number of devices can be reduced by using the inductor required for the first matching circuit **40** simultaneously as the inductor **52** in the second matching circuit **50** as shown in FIG. **8**. As a result, the size of the first matching circuit **40** can be reduced.

That is to say, during reception, there is no problem if only impedance matching is realized between the antenna **80** and the low-noise receiver amplifier **20** by using the devices of the first matching circuit **40** and the second matching circuit. Thus, by comparison to the third embodiment, the design

flexibility of the first matching circuit **40** can be increased. For example, by providing the output terminal **16** of the received signal at such a position of the second matching circuit **50** as to optimize the impedance matching with the low-noise receiver amplifier **20**, the input terminal **31** of the mode switch **30** can also be connected to the output terminal **16** of the received signal. Thus, the number of devices can be reduced simultaneously. In this case, it is naturally possible to apply the respective variations **50A** through **50D** of the second matching circuit **50** shown in FIGS. **5** and **6** and the respective variations of the output terminals **16A** to **16H** of the received signal corresponding to the respective variations.

In addition, since only one switching FET is required, the area occupied by the mode switch **30** and the first matching circuit **40** on the transmitter-receiver circuit can be narrowed, high integration is realized more easily. Ultimately, this fact can contribute more to downsizing and cost reduction of a wireless communication unit incorporating the semiconductor integrated circuit device according to this embodiment.

#### Fifth Embodiment

Hereinafter, the fifth embodiment of the present invention will be described with reference to the drawings.

FIG. **9** is a circuit diagram of a transmitter-receiver circuit for a wireless communication unit according to the fifth embodiment of the present invention.

The fifth embodiment is characterized by the configuration in which the transmission/reception mode switch is not connected between the antenna and the low-noise receiver amplifier as is done in the foregoing embodiments, but is connected between the antenna and the transmitter amplifier. In FIG. **9**, **10** denotes a transmitter amplifier for amplifying an input signal to be transmitted and then outputting the amplified signal. **20** denotes a low-noise receiver amplifier for amplifying an input received signal and then outputting the amplified signal. **30** denotes a mode switch for switching transmission state and reception state in a time-division manner. **40** denotes a first matching circuit for matching the impedance of the input received signal with the input impedance of the low-noise receiver amplifier **20**. **50** denotes a second matching circuit for matching the output impedance of the transmitter amplifier **10** with predetermined impedance. **60** denotes a third matching circuit for matching the impedance of the input signal to be transmitted with the input impedance of a high-power FET **12** of the transmitter amplifier **10**. **70** denotes an interconnection, having characteristic impedance of  $50\Omega$ , for connecting the mode switch **30**, the first matching circuit **40** and an antenna **80** used for both transmission and reception to each other. **71** denotes coupling capacitance for ac coupling the mode switch **30** to the first matching circuit **40**.

In the transmitter amplifier **10** shown in FIG. **9**, **11** denotes an input terminal, through which a signal to be transmitted is input. **12** denotes a high-power FET, of which the gate electrode is provided with the input signal to be transmitted via the third matching circuit **60** and the source is grounded. **13** denotes a power supply terminal connected to the drain electrode of the high-power FET **112**. **15A** denotes an output terminal connected to the input terminal **31** of the mode switch **30**.

In the low-noise receiver amplifier **20** shown in FIG. **9**, **21** denotes an input terminal, through which a received signal is input via the coupling capacitance **71** and the first matching circuit **40**. **22** denotes a low-noise FET, of which the gate electrode is provided with the received signal and the source is grounded. **23** denotes an output terminal connected to the

drain electrode of the low-noise FET 22. 24 denotes a control terminal connected to the gate electrode of the low-noise FET 22.

In the mode switch 30 shown in FIG. 9, 31 denotes an input terminal connected to the output terminal 15 of the transmitter amplifier 10. 32 denotes a switch-control-signal input terminal for controlling a switching FET. 33 denotes an output terminal, through which the amplified signal to be transmitted is output to the antenna 80. 34 denotes a switching FET constituting the mode switch 30.

In the first matching circuit 40 shown in FIG. 9, 41 denotes an input terminal connected to the antenna 80 and to the output terminal 33 of the mode switch 30 via the coupling capacitance 71 and an interconnection having characteristic impedance of  $50\Omega$ . 42 denotes an output terminal connected to the input terminal 21 of the low-noise receiver amplifier 20. 43 denotes a first inductor, one end of which is connected to the input terminal 41 of the first matching circuit 40 and the other end of which is grounded, for constituting the first matching circuit 40. 44 denotes a second inductor, one end of which is connected to the input terminal 41 of the first matching circuit 40 and the other end of which is connected to the output terminal 42, for constituting the first matching circuit 40.

In the second matching circuit 50 shown in FIG. 1, 51 denotes a first capacitor, one end of which is connected to the drain electrode of the high-power FET and the other end of which is grounded, for constituting the second matching circuit 50. 52 denotes an inductor, one end of which is connected to the drain electrode of the high-power FET and the other end of which is connected to a second capacitor 53, for constituting the second matching circuit 50. 53 denotes a second capacitor, one end of which is connected to the inductor 52 and the other end of which is connected to the output terminal 15A of the transmitter amplifier 10, for constituting the second matching circuit 50.

All of the FETs constituting the transmitter amplifier 10, the low-noise receiver amplifier 20 and the mode switch 30 of this transmitter-receiver circuit are assumed to be GaAs FETs or silicon MOSFETs.

Hereinafter, the operation of the transmitter-receiver circuit having the above-described configuration will be described with reference to FIGS. 9 and 10.

FIG. 10 is an equivalent circuit diagram where the transmitter-receiver circuit for a wireless communication unit according to the fifth embodiment of the present invention performs transmitting operation. In FIG. 10, the same components as those of the transmitter-receiver circuit shown in FIG. 9 are identified by the same reference numerals and the description thereof will be omitted herein.

First, the operation thereof during reception will be described.

A less intense received signal, which has been input through the antenna 80, passes through the interconnection 70 having characteristic impedance of  $50\Omega$  and is input to the first matching circuit 40 shown in FIG. 9 via the coupling capacitance 71.

Subsequently, the impedance of the input received signal is matched with the input impedance of the low-noise receiver amplifier 20 by the first matching circuit 40. Thereafter, the signal is input to the input terminal 21 of the low-noise receiver amplifier 20. The input received signal is amplified by the low-noise FET 22 and then output through the output terminal 23 of the low-noise receiver amplifier 20. Since the switching FET 34 has been turned OFF in the mode switch 30, the circuit section on the transmission side is isolated from the antenna 80 and the low-noise receiver amplifier 20.

Next, the operation thereof during transmission will be described.

First, a signal to be transmitted, which has been modulated and amplified to reach a predetermined signal level, is input to the input terminal 11 of the transmitter amplifier 10.

Then, after the impedance of the input signal to be transmitted is matched by the third matching circuit 60 with the input impedance of the high-power FET 12, the input signal to be transmitted is amplified by the high-power FET 12 to gain desired power.

At this point in time, by turning ON the low-noise FET 22 upon the application of a positive voltage, which is equal to larger than Schottky voltage, to the control terminal 24 of the low-noise FET 22 in the low-noise receiver amplifier 20 shown in FIG. 9, the low-noise FET 22 can be equivalent to pure resistance 22A as shown in FIG. 10. Thus, the circuit section on the reception side can be short-circuited during transmission. Accordingly, the output impedance of the transmitter amplifier 10 can be matched with predetermined impedance by the first inductor 43 and the second inductor 44 constituting the first matching circuit 40 and the inductor 52 constituting the second matching circuit 50.

Next, the signal to be transmitted, subjected to the impedance matching, passes through the interconnection 70 having characteristic impedance of  $50\Omega$  and is input to the antenna 80 so as to be output through the antenna 80 as radio waves.

It is noted that the impedance matching should be performed between the first matching circuit and the second matching circuit so that the amplified signal to be transmitted does not flow toward the low-noise receiver amplifier 20.

As can be understood from the above description, in the fifth embodiment, the outputs of the transmitter amplifier 10 are matched by using, in combination, the impedance of the low-noise receiver amplifier 20 during the OFF state and the impedance of the second matching circuit 50 in the transmitter amplifier 10 whereby the low-noise receiver amplifier 20 can be connected to the antenna 80 without interposing any switch. As a result, since a switch for reception can be omitted, it is possible to eliminate the pass loss, which is ordinarily caused by a switch on the input signal of the low-noise receiver amplifier 20.

Furthermore, since the less intense received signal is not attenuated, the S/N ratio during amplification can be increased. Moreover, since only one switching FET is enough, a switch can be downsized and highly integrated.

#### INDUSTRIAL APPLICABILITY

As is apparent from the foregoing description, in the transmitter-receiver circuit for a wireless communication unit according to the present invention, the output terminal of the transmitter amplifier is directly connected to the antenna without passing through the mode switch during transmission. Thus, the pass loss, ordinarily caused by a switch on a signal to be transmitted, can be eliminated. As a result, the power consumption can be reduced. On the other hand, during reception, the circuit section on the transmission side is short-circuited by using the FET for transmission amplification as resistance. As a result, a mode switch on the transmission side is no longer necessary. In other words, a mode switch on the reception side may be constituted by only one switching device, and thus the area occupied by the mode switch in the entire circuit can be reduced. Consequently, the overall size of the transmitter-receiver circuit can be reduced.

On the other hand, since the semiconductor integrated circuit device according to the present invention is consti-

tuted by the transmitter-receiver circuit for a wireless communication unit according to the present invention, the power consumption during transmission can be reduced and the overall size of the transmitter-receiver circuit can be reduced. Thus, the present invention is advantageous for even higher integration. As a result, the costs of a semiconductor integrated circuit device can be reduced.

What is claimed is:

1. A transmitter-receiver circuit for a wireless communication unit, comprising:

- a transmitter amplifier for amplifying and outputting an input signal to be transmitted;
- a receiver amplifier for amplifying and outputting an input received signal; and
- a mode switch, connected to an antenna used for both transmission and reception, for switching a transmission state where the signal to be transmitted, which has been output by the transmitter amplifier, is output to the antenna and a reception state where the received signal, to be input to the receiver amplifier, is input through the antenna,

characterized in that the transmitter amplifier includes:

- an amplifying FET, having a gate electrode connected to an input terminal of the signal to be transmitted, a drain electrode connected to a power supply terminal and a source electrode grounded;
- a matching circuit, connected between the drain electrode of the FET and the antenna, for matching output impedance of the FET with impedance on an antenna side;
- a control terminal connected to the gate electrode of the FET; and
- an output terminal directly connected to the antenna without passing through the mode switch.

2. A transmitter-receiver circuit for a wireless communication unit, comprising:

- a transmitter amplifier for amplifying and outputting an input signal to be transmitted;
- a receiver amplifier for amplifying and outputting an input received signal; and
- a mode switch, connected to an antenna used for both transmission and reception, for switching a transmission state where the signal to be transmitted, which has been output by the transmitter amplifier, is output to the antenna and a reception state where the received signal, to be input to the receiver amplifier, is input through the antenna,

characterized in that the transmitter amplifier includes:

- an amplifying FET, having a gate electrode connected to an input terminal of the signal to be transmitted, a drain electrode connected to a power supply terminal and a source electrode grounded;
- a matching circuit, connected between the drain electrode of the FET and the antenna, for matching output impedance of the FET with impedance on an antenna side;
- a control terminal connected to the gate electrode of the FET; and
- an output terminal directly connected to the antenna without passing through the mode switch,
- and that an input terminal on the antenna side of the mode switch is connected to a terminal of the matching circuit, which is different from an output terminal of the signal to be transmitted of the matching circuit.

3. A semiconductor integrated circuit device, comprising:

- a semiconductor substrate;

a transmitter amplifier, formed on the semiconductor substrate, for amplifying and outputting an input signal to be transmitted;

a receiver amplifier, formed on the semiconductor substrate, for amplifying and outputting an input received signal; and

a mode switch, formed on the semiconductor substrate and connected to an input/output terminal on an antenna side used for both transmission and reception, for switching a transmission state where the signal to be transmitted, which has been output by the transmitter amplifier, is output to the input/output terminal on the antenna side and a reception state where the received signal, to be input to the receiver amplifier, is input through the input/output terminal on the antenna side,

characterized in that the transmitter amplifier includes:

- an amplifying FET, having a gate electrode connected to an input terminal of the signal to be transmitted, a drain electrode connected to a power supply terminal and a source electrode grounded;
- a matching circuit, connected between the drain electrode of the FET and the input/output terminal on the antenna side, for matching output impedance of the FET with impedance on the antenna side;
- a control terminal connected to the gate electrode of the FET; and
- an output terminal directly connected to the input/output terminal on the antenna side without passing through the mode switch.

4. A semiconductor integrated circuit device, comprising:

a semiconductor substrate;

a transmitter amplifier, formed on the semiconductor substrate, for amplifying and outputting an input signal to be transmitted;

a receiver amplifier, formed on the semiconductor substrate, for amplifying and outputting an input received signal; and

a mode switch, formed on the semiconductor substrate and connected to an input/output terminal on an antenna side used for both transmission and reception, for switching a transmission state where the signal to be transmitted, which has been output by the transmitter amplifier, is output to the input/output terminal on the antenna side and a reception state where the received signal, to be input to the receiver amplifier, is input through the input/output terminal on the antenna side,

characterized in that the transmitter amplifier includes:

- an amplifying FET, having a gate electrode connected to an input terminal of the signal to be transmitted, a drain electrode connected to a power supply terminal and a source electrode grounded;
- a matching circuit, connected between the drain electrode of the FET and the input/output terminal on the antenna side, for matching output impedance of the FET with impedance on the antenna side;
- a control terminal connected to the gate electrode of the FET; and
- an output terminal directly connected to the input/output terminal on the antenna side without passing through the mode switch,
- and that an input terminal on the antenna side of the mode switch is connected to a terminal of the matching circuit, which is different from an output terminal of the signal to be transmitted of the matching circuit.